AirPrime MC7421

Product Technical Specification

DRAFT

SIERRA WIRELESS®

Important Notice

Due to the nature of wireless communications, transmission and reception of data can never be guaranteed. Data may be delayed, corrupted (i.e., have errors) or be totally lost. Although significant delays or losses of data are rare when wireless devices such as the Sierra Wireless modem are used in a normal manner with a well-constructed network, the Sierra Wireless modem should not be used in situations where failure to transmit or receive data could result in damage of any kind to the user or any other party, including but not limited to personal injury, death, or loss of property. Sierra Wireless accepts no responsibility for damages of any kind resulting from delays or errors in data transmitted or received using the Sierra Wireless modem, or for failure of the Sierra Wireless modem to transmit or receive such data.

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Do not operate the Sierra Wireless modem in areas where blasting is in progress, where explosive atmospheres may be present, near medical equipment, near life support equipment, or any equipment which may be susceptible to any form of radio interference. In such areas, the Sierra Wireless modem **MUST BE POWERED OFF**. The Sierra Wireless modem can transmit signals that could interfere with this equipment.

Do not operate the Sierra Wireless modem in any aircraft, whether the aircraft is on the ground or in flight. In aircraft, the Sierra Wireless modem **MUST BE POWERED OFF**. When operating, the Sierra Wireless modem can transmit signals that could interfere with various onboard systems.

Note: Some airlines may permit the use of cellular phones while the aircraft is on the ground and the door is open. Sierra Wireless modems may be used at this time.

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Revision History

Revision number	Release date	Changes
1	March 2020	Initial release.
2	April 2020	Updated Carrier Aggregation Download Combinations Updated Figure 6-2

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1: Introduction

The Sierra Wireless MC7421 PCI Express Mini Card is a compact, lightweight, wireless modem that provides LTE, UMTS, and GNSS connectivity for M2M applications, notebook, ultrabook and tablet computers over several radio frequency bands.

Supported RF Bands

The module, based on Qualcomm's MDM9250 baseband processor, supports data operation on LTE and UMTS networks over the bands described in Table 1-1, with LTE carrier aggregation (CA) as described in Table 1-2 and Table 1-3.

Table 1-1: Supported RF Bands

RAT	Bands												
	1	3	5	7	8	20	28	32	38	40	41	42	43
LTE[a]	F	F		F	F	F	F	F	T	T	T	T	T
UMTS[b]	Y		Y		Y								
GNSS	- GPS: 1575.42 MHz - GLONASS: 1602 MHz - BeiDou: 1561.098 MHz - Galileo: 1575.42 MHz												

a. (LTE) Downlink MIMO support (2x2; 4x2)
    F=FDD; T=TDD
    Data rates: Downlink (Cat 7 with 2CA, 64QAM=300 Mbps), Uplink (Cat 13 with 2CA contiguous, 64QAM=150 Mbps)
b. UMTS (DC-HSPA+, HSPA+, HSPA, UMTS)
    Diversity support
    Data rates: Downlink (Cat 24, up to 42 Mbps), Uplink (Cat 6, up to 5.76 Mbps)

Table 1-2: Carrier Aggregation Downlink Combinations

1 Band / 2CC	2 Bands / 2CC
CA_1A-1A	CA_1A-8A
CA_1C	CA_1A-20A
	CA_1A-28A
CA_3A-3A	CA_3A-7A
CA_3C	CA_3A-8A
	CA_3A-20A
	CA_3A-28A
CA_7A-7A	CA_7A-8A
CA_7B	CA_7A-20A
CA_7C	CA_7A-28A

Table 1-2: Carrier Aggregation Downlink Combinations (Continued)

1 Band / 2CC	2 Bands / 2CC
	CA_20A-32A
CA_38A-38A	
CA_38C	
CA_40A-40A	
CA_40C	
CA_41A-41A	
CA_41C	
CA_42A-42A	
CA_42C	

Table 1-3: Carrier Aggregation Uplink Combinations

CA_1C
CA_3C
CA_7C
CA_41C

Physical Features

- Small form factor—conforms to type F2 as specified in *PCI Express Mini Card Electromechanical Specification Revision 1.2*.
- Ambient operating temperature range:
  - Class A (3GPP compliant): -30°C to +70°C
  - Class B (operational, non-3GPP compliant): -40°C to +85°C (reduced operating parameters required)

Important: *The internal module temperature (reported by AT!PCTEMP) must be kept below 93°C. For best performance, the internal module temperature should be kept below 80°C. Proper mounting, heat sinks, and active cooling may be required, depending on the integrated application.*

Application Interface Features

- USB interface (QMI) for Windows 7 and legacy Windows operating systems
- MBIM for Windows 8.1 and Windows 10
- AT command interface (*[1] AT Command Set for User Equipment (UE) (Release 6) (Doc# 3GPP TS 27.007)*, plus proprietary extended AT commands in *[2] AirPrime EM74xx/MC74xx AT Command Reference (Doc# 4117727)*)

- Software Development Kits (SDK),including API (Application Program Interface) functions:
  - Windows 10
  - Linux
- Support for active antenna control via dedicated antenna control signals (ANT_CTRL0:2)
- Dynamic power reduction support via software and dedicated signal (DPR)
- OMA DM (Open Mobile Alliance Device Management)
- FOTA (Firmware Over The Air)

Note: OMA DM and FOTA support is operator-dependent.

Modem Features

- LTE / DC-HSPA+ / HSPA+ / HSPA / UMTS (WCDMA) operation
- Multiple (up to 16) cellular packet data profiles
- Traditional modem COM port support for AT commands
- USB suspend / resume
- Sleep mode for minimum idle power draw
- SIM application tool kit with proactive SIM commands
- Enhanced Operator Name String (EONS)
- Mobile-originated PDP context activation / deactivation
- Support QoS QCI (3GPP Release 12)
- Static and Dynamic IP address. The network may assign a fixed IP address or dynamically assign one using DHCP (Dynamic Host Configuration Protocol).
- PAP and CHAP support
- PDP context type (IPv4, IPv6, or IPv4v6)
- RFC1144 TCP/IP header compression

LTE Features

- Carrier aggregation:
- Carrier aggregation:
  - DL LTE-FDD—40 MHz
  - DL LTE-TDD—40 MHz
  - UL LTE—40 MHz intraband contiguous
- CSG support (LTE Femto)
- LTE Advanced receivers (NLIC, eICIC, feICIC)
- Basic cell selection and system acquisition
  - PSS/SSS/MIB decode
  - SIB1–SIB16 decoding
- NAS/AS security procedures
  - Snow 3G/AES/ZUC security
- CQI/RI/PMI reporting
- Paging procedures
  - Paging in Idle and Connected mode

- Dedicated bearer
  - Network-initiated dedicated bearer
  - UE-initiated dedicated bearer
- Multiple PDN connections (IPv4 and IPv6 combinations), subject to operating system support.
- Connected mode intra-LTE mobility
- Idle mode intra-LTE mobility
- iRAT between LTE/3G for idle and connection release with redirection
- Detach procedure
  - Network-initiated detach with reattach required
  - Network-initiated detach followed by connection release

Short Message Service (SMS) Features

- Mobile-originated and mobile-terminated SMS over IMS for LTE
- Mobile-originated and mobile-terminated SMS over SGs for LTE

Position Location (GNSS)

- Customizable tracking session
- Automatic tracking session on startup
- Concurrent standalone GPS, GLONASS, and BeiDou
- Concurrent standalone Galileo
- Assisted GPS (A-GPS) SUPL1.0
- Assisted GPS/GLONASS SUPL2.0
- GPS/GLONASS on dedicated connector or diversity connector
- BeiDou on dedicated connector, or on diversity connector with reduced performance
- Galileo on dedicated connector or diversity connector

Supporting Documents

Several additional documents describe Mini Card design, usage, integration, and other features. See References on page 58.

Accessories

The Universal Development Kit (UDK) is a hardware development platform for AirPrime MC-series modules. It contains hardware components for evaluating and developing with the module, including:

- Development board
- Cables
- Antennas (Additional antennas may be required to support all bands.)
- Initial allotment of support hours
- Other accessories

For instructions on setting up the UDK, see *[3] PCI Express Mini Card Dev Kit Quick Start Guide (Doc# 2130705)*.

For over-the-air LTE testing, ensure that suitable antennas are used. (Two antennas are required for this testing.)

Required Connectors

Table 1-4 describes the connectors used to integrate AirPrime MC-series modules into your host device.

Table 1-4: Required Host-Module Connectors[a]

Connector type	Description
RF cables	• Mate with Hirose U.FL connectors (model U.FL #CL331-0471-0-10) • Three connector jacks
EDGE (52-pin)	• Industry-standard mating connector • Some manufacturers include Tyco, Foxconn, Molex • Example: UDK board uses Molex 67910-0001
SIM	• Industry-standard connector. Type depends on how host device exposes the SIM socket • Example: UDK board uses ITT CCM03-3518

a. Manufacturers/part numbers are for reference only and are subject to change. Choose connectors that are appropriate for your own design.

Ordering Information

To order, contact the Sierra Wireless Sales Desk at +1 (604) 232-1488 between 8 AM and 5 PM Pacific Time.

Integration Requirements

Sierra Wireless provides, in the document suite, guidelines for successful Mini Card integration and offers integration support services as necessary.

When integrating the MC7421 PCI-Express Mini Card, the following items need to be addressed:
• **Mounting**—Effect on temperature, shock, and vibration performance
• **Power supply**—Impact on battery drain and possible RF interference
• **Antenna location and type**—Impact on RF performance
• **Regulatory approvals**—As discussed in Regulatory Compliance and Industry Certifications on page 50.
• **Service provisioning**—Manufacturing process
• **Software**—As discussed in Software Interface on page 45.
• **Host Interface**—Compliance with interface voltage levels

2: Electrical Specifications

The module includes the following interfaces to the host:
- Power—Supplied to the module by the host.
- W_DISABLE_N—Input supplied to the module by the host to cause the module to either turn off/on or enter/exit low power mode (software configurable).
- WAKE_N— Signal used to wake the host when specific events occur.
- WAN_LED_N—Active-low LED drive signal provides an indication of WAN radio ON state.
- SYSTEM_RESET_N—Active-low reset input.
- Antenna—Three U.FL RF connectors (main (Rx/Tx), GNSS, and auxiliary (diversity/ MIMO/GNSS). For details, see RF Specifications on page 29.
- Antenna control—Three signals that can be used to control external antenna switches.
- Dynamic power control—Signal used to adjust Tx power to meet CE SAR requirements. For details, see Tx Power Control on page 44.
- Dual SIM—Supported through the interface connector. The SIM cavities / connectors must be placed on the host device for this feature.
- USB—USB 2.0 and USB 3.0 interfaces to the host for data, control, and status information.

The MC7421 has two main interface areas—the host I/O connector and the RF ports. Details of these interfaces are described in the sections that follow.

Host Interface Pin Assignments

The MC7421 host I/O connector provides pins for power, serial communications, and control. Pin assignments are listed in Table 2-1.

Refer to the following tables for pin details based on interface types:
- Table 2-2, Power and Ground Specifications, on page 20
- Table 2-3, USB Interfaces, on page 20
- Table 2-4, SIM Interface Signals, on page 22
- Table 2-5, Module Control Signals, on page 25

Note: On any given interface (USB, SIM, etc.), leave unused inputs and outputs as no-connects.

Note: The host should not drive any signals to the module until > 100 ms from start of power-on sequence.

Table 2-1: Connector Pin Assignments[a]

Pin	Signal name	Pin type[b]	Description	Direction[c]	Active state	Voltage levels (V) Min	Typ	Max
1	WAKE_N	OC	Wake host	Output	Low	-	-	0.10
2	VCC	V	Power supply	Input	Power	3.135	3.30	3.60

Table 2-1: Connector Pin Assignments[a] (Continued)

Pin	Signal name	Pin type[b]	Description	Direction[c]	Active state	Voltage levels (V) Min	Typ	Max
3	ANT_CTRL0 / GPIO1	-	(ANT_CTRL0) Customer-defined external switch control for multiple antennas	Output	High	1.35	1.80	1.90
				Output	Low	0	-	0.45
			(GPIO1) General purpose I/O	Input High		1.17	1.80	2.10
				Input Low		-0.30		0.63
				Output High		1.35	1.80	1.90
				Output Low		0.00		0.45
4	GND	V	Ground	Input	Power	-	0	-
5	ANT_CTRL1 / GPIO2	-	(ANT_CTRL1) Customer-defined external switch control for multiple antennas	Output	High	1.35	1.80	1.90
				Output	Low	0	-	0.45
			(GPIO2) General purpose I/O	Input High		1.17	1.80	2.10
				Input Low		-0.30		0.63
				Output High		1.35	1.80	1.90
				Output Low		0.00		0.45
6	NC	-	No connect	-	-	-	-	-
7	USIM2_RST	-	SIM 2 Reset	Output	Low	0	-	0.45
					High	2.55 (3V SIM) 1.35 (1.8V SIM)	-	3.10 (3V SIM) 1.90 (1.8V SIM)
8	USIM_PWR	-	SIM VCC supply	Output	Power	2.90 (3V SIM) 1.75 (1.8V SIM)	3.00 (3V SIM) 1.80 (1.8V SIM)	3.10 (3V SIM) 1.85 (1.8V SIM)
9	GND	V	Ground	Input	Power	-	0	-
10	USIM_DATA	-	SIM IO pin	Input	Low	-0.30 (3V SIM) -0.30 (1.8V SIM)	-	0.60 (3V SIM) 0.35 (1.8V SIM)
					High	2.10 (3V SIM) 1.17 (1.8V SIM)	3.00 (3V SIM) 1.80 (1.8V SIM)	3.30 (3V SIM) 2.10 (1.8V SIM)
				Output	Low	0	-	0.40
					High	2.55 (3V SIM) 1.35 (1.8V SIM)	3.00 (3V SIM) 1.80 (1.8V SIM)	3.10 (3V SIM) 1.90 (1.8V SIM)
11	VREF_1.8V[d]	-	1.8V reference voltage output	Output	Power	1.75	1.80	1.85

Table 2-1: Connector Pin Assignments[a] (Continued)

Pin	Signal name	Pin type[b]	Description	Direction[c]	Active state	Voltage levels (V)		
						Min	Typ	Max
12	USIM_CLK	-	SIM Clock	Output	Low	0	-	0.45
					High	2.55 (3V SIM) 1.35 (1.8V SIM)	3.00 (3V SIM) 1.80 (1.8V SIM)	3.10 (3V SIM) 1.90 (1.8V SIM)
13	USIM2_PWR	-	SIM 2 VCC supply	Output	Power	2.90 (3V SIM) 1.75 (1.8V SIM)	3.00 (3V SIM) 1.80 (1.8V SIM)	3.10 (3V SIM) 1.85 (1.8V SIM)
14	USIM_RST	-	SIM Reset	Output	Low	0	-	0.45
					High	2.55 (3V SIM) 1.35 (1.8V SIM)	3.00 (3V SIM) 1.80 (1.8V SIM)	3.10 (3V SIM) 1.90 (1.8V SIM)
15	GND	V	Ground	Input	Power	-	0	-
16	NC	-	No connect	-	-	-	-	-
17	USIM2_CLK	-	SIM 2 Clock	Output	Low	0	-	0.45
					High	2.55 (3V SIM) 1.35 (1.8V SIM)	3.00 (3V SIM) 1.80 (1.8V SIM)	3.10 (3V SIM) 1.90 (1.8V SIM)
18	GND	V	Ground	Input	Power	-	0	-
19	USIM2_DATA	-	SIM 2 IO pin	Input	Low	-0.30 (3V SIM) -0.30 (1.8V SIM)	-	0.60 (3V SIM) 0.35 (1.8V SIM)
					High	2.10 (3V SIM) 1.17 (1.8V SIM)	3.00 (3V SIM) 1.80 (1.8V SIM)	3.30 (3V SIM) 2.10 (1.8V SIM)
				Output	Low	0	-	0.40
					High	2.55 (3V SIM) 1.35 (1.8V SIM)	3.00 (3V SIM) 1.80 (1.8V SIM)	3.10 (3V SIM) 1.90 (1.8V SIM)
20	W_DISABLE_N[e]	PU	Module power state control	Input	Low	-0.30	-	0.40
21	GND	V	Ground	Input	Power	-	0	-
22	SYSTEM_RESET_N[f]	PU	Reset	Input	Low	-0.30	-	0.63
23	USB3.0_TX-		USB 3.0 Transmit Data negative	Output	Differential	-	-	-
24	VCC	V	Power supply	Input	Power	3.135	3.30	3.60
25	USB3.0_TX+		USB 3.0 Transmit Data positive	Output	Differential	-	-	-
26	GND	V	Ground	Input	Power	-	0	-
27	GND	V	Ground	Input	Power	-	0	-
28	NC	-	No connect	-	-	-	-	-
29	GND	V	Ground	Input	Power	-	0	-

Table 2-1: Connector Pin Assignments[a] (Continued)

Pin	Signal name	Pin type[b]	Description	Direction[c]	Active state	Voltage levels (V) Min	Typ	Max
30	NC		Reserved— Host must not repurpose this pin.					
31	USB3.0_RX-		USB 3.0 Receive Data negative	Input	Differential	-	-	-
32	NC		Reserved— Host must not repurpose this pin.					
33	USB3.0_RX+		USB 3.0 Receive Data positive	Input	Differential	-	-	-
34	GND	V	Ground	Input	Power	-	0	-
35	GND	V	Ground	Input	Power	-	0	-
36	USB_D-	-	USB data negative	Input/Output	Differential	-	-	-
37	GND	V	Ground	Input	Power	-	0	-
38	USB_D+	-	USB data positive	Input/Output	Differential	-	-	-
39	VCC	V	Power supply	Input	Power	3.135	3.30	3.60
40	GND	V	Ground	Input	Power	-	0	-
41	VCC	V	Power supply	Input	Power	3.135	3.30	3.60
42	WAN_LED_N	OC	LED Driver	Output	Low	0	-	0.15
43	GND	V	Ground	Input	Power	-	0	-
44	ANT_CTRL2 / GPIO3	-	(ANT_CTRL2) Customer-defined external switch control for multiple antennas	Output	High	1.35	1.80	1.90
				Output	Low	0	-	0.45
			(GPIO3) General purpose I/O	Input High		1.17	1.80	2.10
				Input Low		-0.30		0.63
				Output High		1.35	1.80	1.90
				Output Low		0.00		0.45
45	NC		Reserved— Host must not repurpose this pin.					

Table 2-1: Connector Pin Assignments[a] (Continued)

Pin	Signal name	Pin type[b]	Description	Direction[c]	Active state	Voltage levels (V) Min	Typ	Max
46	DPR/ GPIO4	-	(DPR) Dynamic power control	Input	High	1.17	1.80	2.10
				Input	Low	-0.30	-	0.63
			(GPIO4) General purpose I/O	Input High		1.17	1.80	2.10
				Input Low		-0.30		0.63
				Output High		1.35	1.80	1.90
				Output Low		0.00		0.45
47	NC		Reserved—Host must not repurpose this pin.					
48	NC	-	No connect	-	-	-	-	-
49	NC		Reserved—Host must not repurpose this pin.					
50	GND	V	Ground	Input	Power	-	0	-
51	NC		Reserved—Host must not repurpose this pin.					
52	VCC	V	Power supply	Input	Power	3.135	3.30	3.60

a. The host should leave all 'NC' ('no connect) pins unconnected.
b. A—Analog; I—Input; NP—No pull; O—Digital output; OC—Open Collector; PU—Digital input (internal pull up); PD—Digital output (internal pull down); V—Power or ground
c. Signal directions are from module's point of view (e.g. 'Output' from module to host, 'Input' to module from host.)
d. To avoid adverse effects on module operation, do not draw more than 10 mA current on pin 11.
e. Sierra Wireless recommends that the host implement an open collector driver where a Low signal will turn the module off or enter low power mode, and a high signal will turn the module on or leave low power mode.
f. The module must not be plugged into a port that supports PCI Express—the pin is used by a PCIE signal, which can cause the module to be in reset state or occasionally reset.

Power Supply

The host provides power to the MC7421 through multiple power and ground pins as summarized in Table 2-2.

The host must provide safe and continuous power at all times; the module does not have an independent power supply, or protection circuits to guard against electrical issues.

Table 2-2: Power and Ground Specifications

Name	Pins	Specification	Min	Typ	Max	Units
VCC	2, 24, 39, 41, 52	Voltage range	See Table 2-1 on page 15.			
		Ripple voltage	-	-	100	mV$_{pp}$
GND	4, 9, 15, 18, 21, 26, 27, 29, 34, 35, 37, 40, 43, 50	-	-	0	-	V

USB Interface

Important: *Host support for USB 2.0 (high speed) signals is required.*

Important: *Host support for USB 3.0 signals is optional, but if supported then the host must also support fallback to USB 2.0.*

The device supports USB 2.0 (high speed) and USB 3.0 interfaces for communication between the host and module.

Important: *USB 2.0 full speed and low speed are not supported.*

The interfaces comply with the *[10] Universal Serial Bus Specification, Rev 2.0* and *[11] Universal Serial Bus Specification, Rev 3.0* (subject to limitations described below), and the host device must be designed to the same standards.

Table 2-3: USB Interfaces

	Name	Pin	Description
USB 2.0	USB_D-	36	USB data negative
	USB_D+	38	USB data positive
USB 3.0	USB3.0_TX-[a]	23	Transmit data negative
	USB3.0_TX+[a]	25	Transmit data positive
	USB3.0_RX-[a]	31	Receive data negative
	USB3.0_RX+[a]	33	Receive data positive

a. Signal directions (Tx/Rx) are from device's point of view.

Host-side Recommendation

Note: When designing the host device, careful PCB layout practices must be followed.

Sierra Wireless recommends the host platform include series capacitors on the USB3.0 Rx signals (no capacitors required for the Tx signals), as shown below.
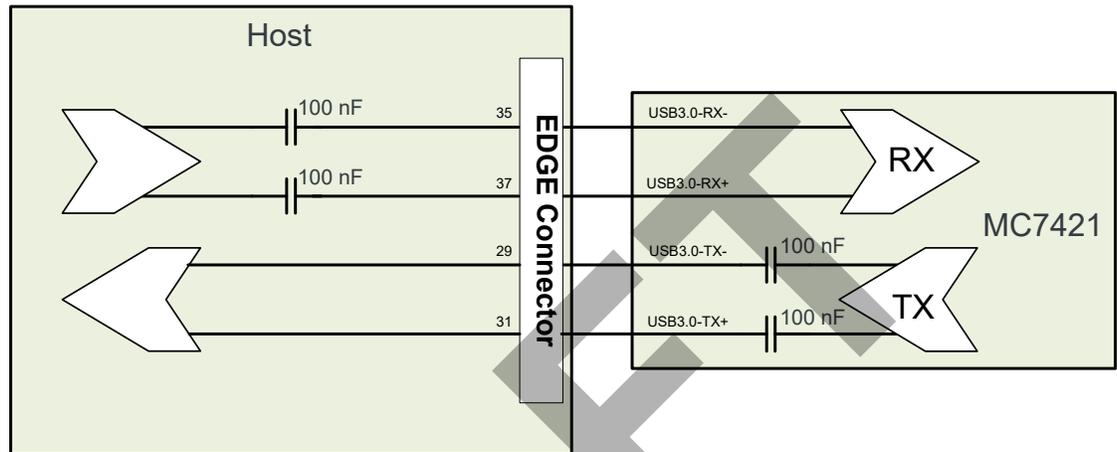

Figure 2-1: Recommended Capacitor Placement for USB3.0 Signals

USB Throughput Performance

This device has been designed to achieve optimal performance and maximum throughput using USB superspeed mode (USB 3.0). Although the device may operate with a high speed host, throughput performance will be on an "as is" basis and needs to be characterized by the OEM. Note that throughput will be reduced and may vary significantly based on packet size, host interface, and firmware revision.

User-developed Drivers

Details for user-developed USB drivers are described in *[4] AirCard/AirPrime USB Driver Developer's Guide (Doc# 2130634).*

SIM Interface

Note: Host support for SIM interface signals is required.

The module supports up to two SIMs (Subscriber Identity Module) (1.8 V or 3 V). Each SIM holds information for a unique account, allowing users to optimize their use of each account on multiple devices.
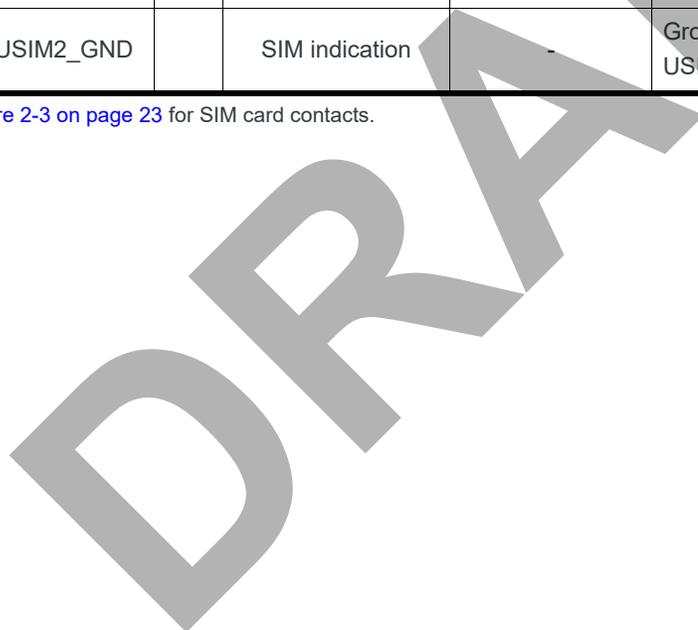
The SIM pins (Table 2-4) provide the connections necessary to interface to SIM sockets located on the host device as shown in Figure 2-2 on page 23. Voltage levels over this interface comply with 3GPP standards.

The types of SIM connectors used depends on how the host device exposes the SIM sockets.

Table 2-4: SIM Interface Signals

SIM	Name	Pin	Description	SIM contact number[a]	Notes
Primary	USIM_PWR	8	SIM voltage	1	Power supply for SIM
	USIM_DATA	10	Data I/O	7	Bi-directional SIM data line
	USIM_CLK	12	Serial clock	3	Serial clock for SIM data
	USIM_RST	14	Reset	2	Active low SIM reset
	USIM_GND		Ground	5	Ground reference USIM_GND is common to module ground
Secondary	USIM2_PWR	13	SIM voltage	2	Power supply for SIM 2
	USIM2_DATA	19	Data I/O	3	Bi-directional SIM 2 data line
	USIM2_CLK	17	Serial clock	7	Serial clock for SIM 2 data
	USIM2_RST	7	Reset	1	Active low SIM 2 reset
	USIM2_GND		SIM indication	-	Ground reference USIM2_GND is common to module ground

a.   See for SIM card contacts.

4.7uF
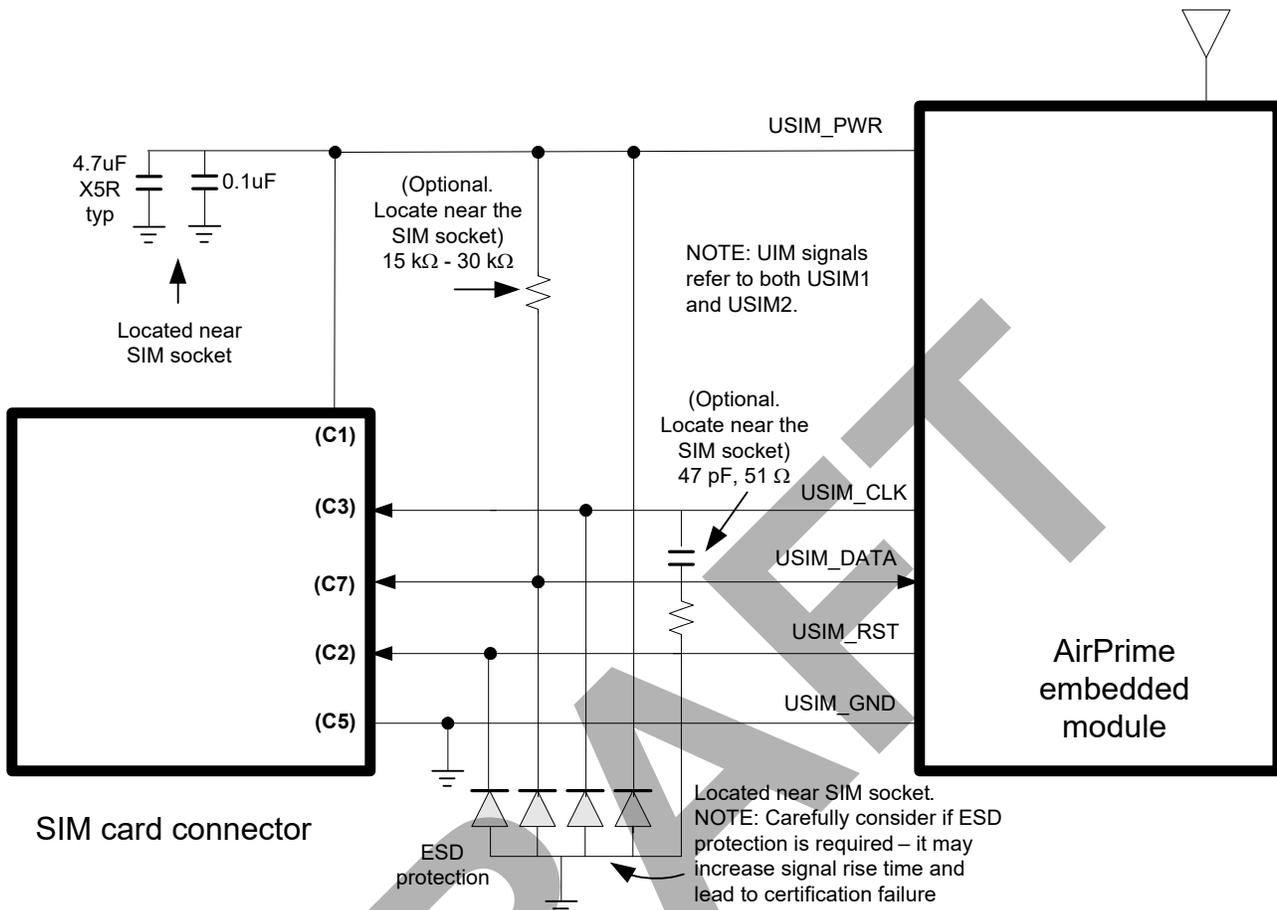X5R
typ

0.1uF

Located near
SIM socket

(Optional.
Locate near the
SIM socket)
15 kΩ - 30 kΩ

USIM_PWR

NOTE: UIM signals
refer to both USIM1
and USIM2.

(Optional.
Locate near the
SIM socket)
47 pF, 51 Ω

(C1)

(C3)   USIM_CLK

(C7)   USIM_DATA

(C2)   USIM_RST

(C5)   USIM_GND

AirPrime
embedded
module

SIM card connector

ESD
protection

Located near SIM socket.
NOTE: Carefully consider if ESD
protection is required – it may
increase signal rise time and
lead to certification failure

Figure 2-2: SIM Application Interface (applies to both SIM interfaces)

Contact View (notched corner at top left)

RFU | C8
I/O | C7
VPP | C6
GND | C5
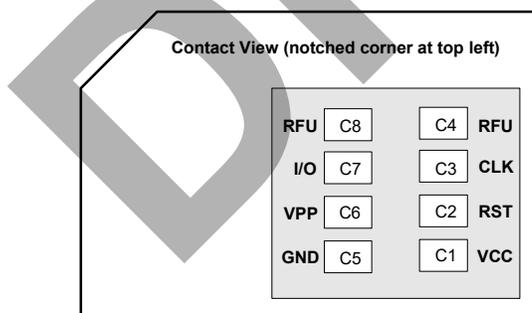
C4 | RFU
C3 | CLK
C2 | RST
C1 | VCC

Figure 2-3: SIM Card Contacts (Contact View)

SIM Implementation

Note: For interface design requirements, refer to ETSI TS 102 230 V5.5.0, section 5.2.

When designing the remote SIM interface, you *must* make sure that SIM signal integrity is not compromised.

Some design recommendations include:

- Total impedance of the VCC and GND connections to the SIM, measured at the module connector, should be less than 1 Ω to minimize voltage drop (includes any trace impedance and lumped element components—inductors, filters, etc.).
- Position the SIM connector ≤10 cm from the module. If a longer distance is required because of the host device design, use a shielded wire assembly—connect one end as close as possible to the SIM connector and the other end as close as possible to the module connector. The shielded assembly may help shield the SIM interface from system noise.
- Reduce crosstalk on the USIM_DATA and USIM2_DATA lines to reduce the risk of failures during GCF approval testing.
- Avoid routing the clock and data lines for each SIM (USIM_CLK/USIM_DATA, USIM2_CLK/USIM2_DATA) in parallel over distances >2 cm—cross-coupling of a clock and data line pair can cause failures.
- 3GPP has stringent requirements for I/O rise time (<1 µs), signal level limits, and noise immunity—consider this carefully when developing your PCB layout.
  - Keep signal rise time <1 µs—keep SIM signals as short as possible, and keep very low capacitance traces on the data and clock signals (USIM_CLK, USIM_DATA, USIM2_CLK, USIM2_DATA). High capacitance increases signal rise time, potentially causing your device to fail certification tests.
- Add external pull-up resistors (15 kΩ–30 kΩ), if required, between the data and power lines for each SIM (USIM_DATA/USIM_PWR, USIM2_DATA/USIM2_PWR) to optimize the signal rise time.
- VCC line should be decoupled close to the SIM socket.
- SIM is specified to run up to 5 MHz (SIM clock rate). Take note of this speed in the placement and routing of the SIM signals and connectors.
- You must decide whether additional ESD protection is required for your product, as it is dependent on the application, mechanical enclosure, and SIM connector design. The SIM pins will require additional ESD protection if they are exposed to high ESD levels (i.e. can be touched by a user).
- Putting optional decoupling capacitors on the SIM power lines (USIM_PWR, USIM2_PWR) near the SIM sockets is recommended—the longer the trace length (impedance) from the socket to the module, the greater the capacitance requirement to meet compliance tests.
- Putting an optional series capacitor and resistor termination (to ground) on the clock lines (USIM_CLK, USIM2_CLK) at the SIM sockets to reduce EMI and increase signal integrity is recommended if the trace length between the SIM socket and module is long—47 pF and 50 Ω resistor are recommended.
- Test your first prototype host hardware with a Comprion IT[3] SIM test device at a suitable testing facility.

Control Interface (Signals)

The MC7421 provides signals for:
- Waking the host when specific events occur
- Host control of module power
- LED driver output

Note: Host support for W_DISABLE_N is required, and support for other signals in Table 2-5 is optional.

These signals are summarized in Table 2-5 and paragraphs that follow.

Table 2-5: Module Control Signals

Name	Pin	Description	Type[a]
WAKE_N	1	Wake host	OC
W_DISABLE_N	20	On/off signal[b]	PU
SYSTEM_RESET_N	22	Reset module (input from host)	PU
WAN_LED_N	42	LED driver	OC

a. OC—Open Collector; PU—Digital pin Input, internal pull up
b. W_DISABLE_N causes the module to either turn off/on or enter/leave low power mode (software configurable).

WAKE_N — Wake Host

Note: Host support for WAKE_N is optional.

The module uses WAKE_N to wake the host when specific events occur.

The host must provide a 5 kΩ–100 kΩ pullup resistor that considers total line capacitance (including parasitic capacitance) such that when WAKE_N is deasserted, the line will rise to 3.3 V (Host power rail) in < 100 ns.

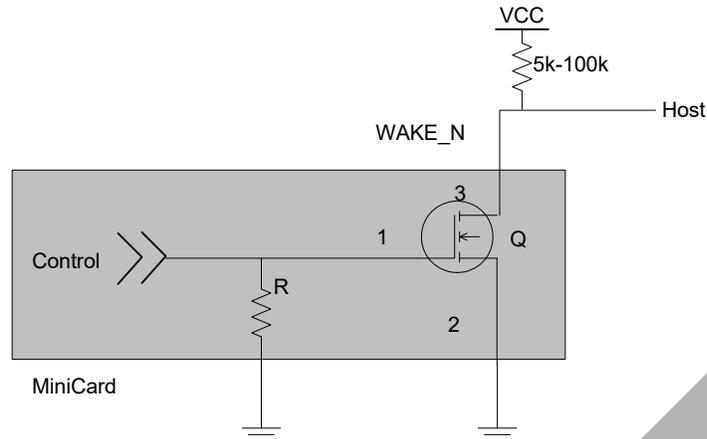See Figure 2-4 on page 26 for a recommended implementation.

Figure 2-4: Recommended WAKE_N Connection

W_DISABLE_N — Wireless Disable

Note: Host support for W_DISABLE_N is required.

The host uses W_DISABLE_N to cause the module to either turn off/on or enter/leave low power mode, as described in Table 2-6.

For timing details, see .

Table 2-6: W_DISABLE_N Usage

Name	Pin	Description/notes
W_DISABLE_N	20	Powers the module on/off (or enters/leaves low power mode)[a]. • Leave as not connected or drive HIGH to keep the modem always on • Drive LOW to turn the module off (or enter low power mode). • An AT command may be used to configure this signal so the module enters low power mode instead of powering off.

a. Sierra Wireless recommends that the host implement an open collector driver where a Low signal will turn the module off or enter low power mode, and a high signal will turn the module on or leave low power mode.

WAN_LED_N—LED Output

Note: Host support for WAN_LED_N is optional.

The module drives the LED output according to *[9] PCI Express Mini Card Electromechanical Specification Revision 2.1*.

The LED configuration is customizable. Contact your Sierra Wireless account representative for details.
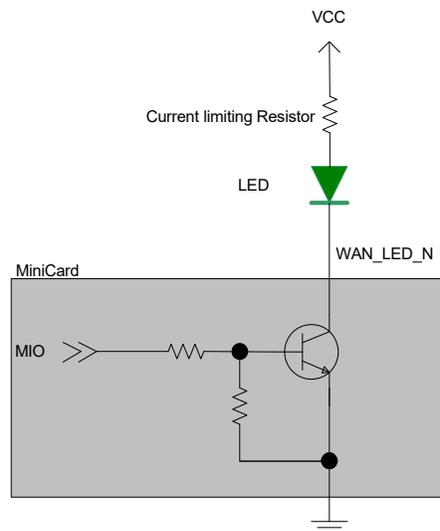
Figure 2-5: Example LED

SYSTEM_RESET_N—Reset Input

Note: Host support for SYSTEM_RESET_N is optional.

SYSTEM_RESET_N has an internal 1.8 V internal pull up that requires an open collector input from the host.

To reset the module, pulse SYSTEM_RESET_N with a logic low signal for 3 seconds (min) to 5.5 seconds (max) — if the signal is held low for more than 5.5 seconds, the reset cycle restarts, and if it is held low through several cycles, the module will not fully boot.
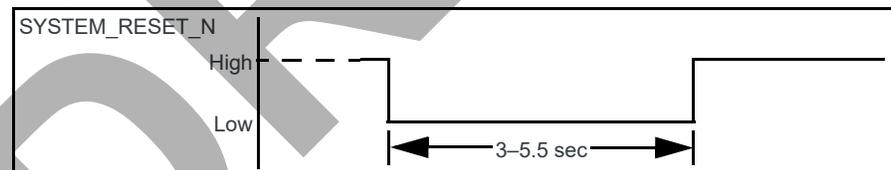

Figure 2-6: SYSTEM_RESET_N reset timing

Otherwise, leave the signal floating or high impedance (the module will remain operational because the module has a pull-up resistor to an internal reference voltage (1.8V) in place.).

Note: The module must not be plugged into a port that supports PCI Express— SYSTEM_RESET_N is carried on a pin that is used for a PCIE signal, which can cause the module to be in reset state or occasionally reset.

Antenna Control

*Note: Host support for antenna control signals is optional.*

The MC7421 Mini Card provides three output signals (listed in Table 2-7) that may be used for host designs that incorporate tunable antennas.

Customers can configure these signals as appropriate for the operating band(s) using the command AT!ANTSEL. (See *[2] AirPrime EM74xx/MC74xx AT Command Reference (Doc# 4117727)* for details.)

Note: To avoid detuning the PCC band, customers must make sure there are no GPIO state conflicts between the PCC and SCC for all supported CA combinations.

Table 2-7: Antenna Control Signals

Name	Pin	Description
ANT_CTRL0	3	
ANT_CTRL1	5	Customer-defined external switch control for tunable antennas
ANT_CTRL2	44	
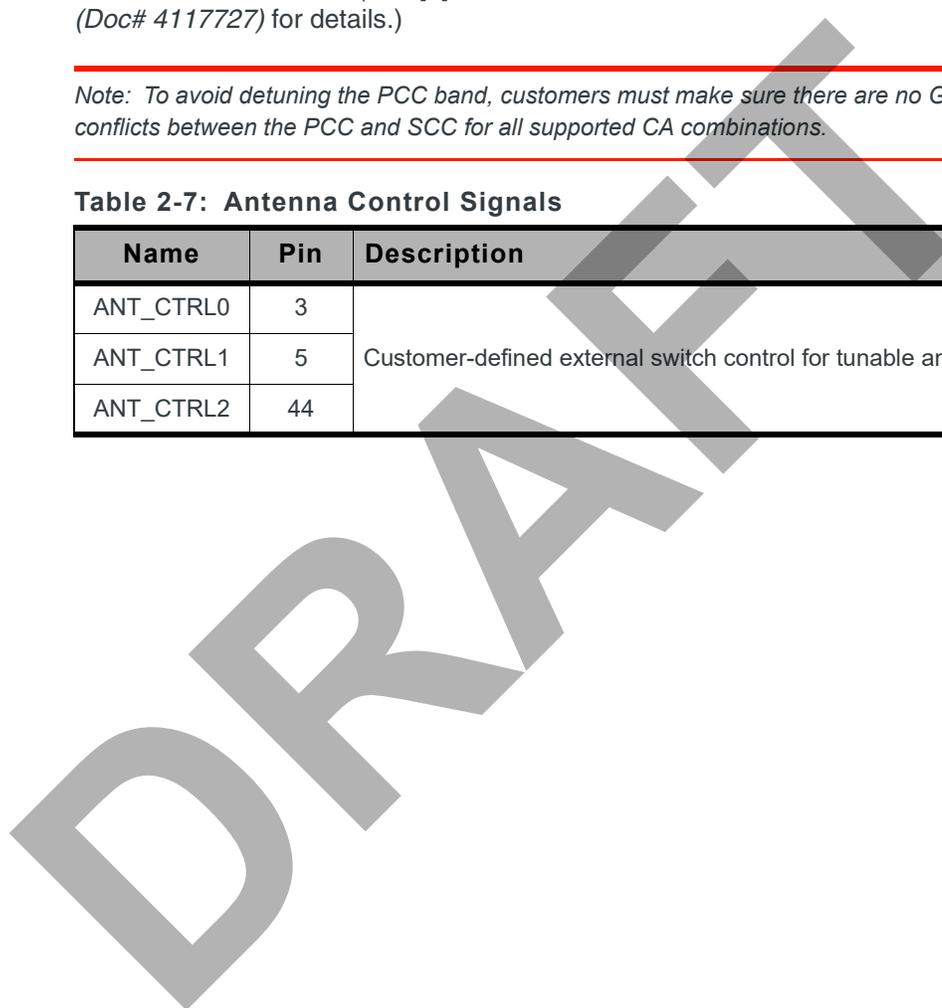
3: RF Specifications

The MC7421 includes three RF connectors for use with host-supplied antennas:
- Main RF connector—Tx/Rx path
- GNSS RF connector—Dedicated GPS, GLONASS, BeiDou, and Galileo
- Auxiliary RF connector—Diversity, MIMO, GPS, GLONASS, and Galileo

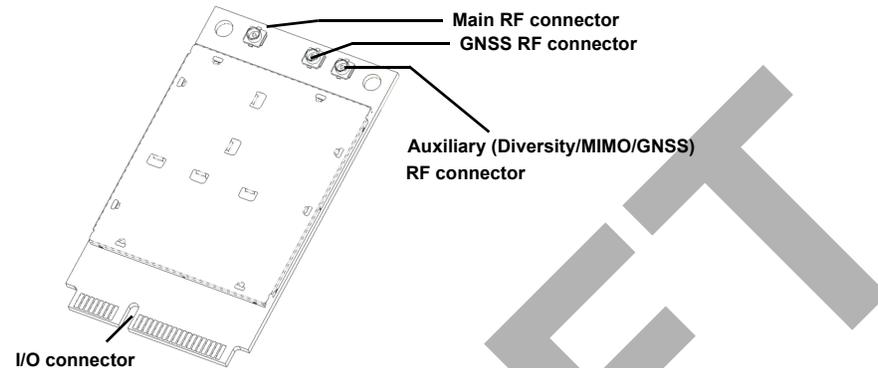The module does not have integrated antennas.

Figure 3-1: Module Connectors (Preliminary shield design, subject to change)

RF Connections

When attaching antennas to the module:
- Use Hirose U.FL connectors (3 mm x 3 mm, low profile; model U.FL #CL331-0471-0-10) to attach antennas to connection points on the module, as shown in Figure 3-1 on page 29.

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*Note: To **disconnect** the antenna, make sure you use the Hirose U.FL connector removal tool (P/N UFL-LP-N-2(01)) to prevent damage to the module or coaxial cable assembly.*

- Match coaxial connections between the module and the antenna to 50 Ω.
- Minimize RF cable losses to the antenna; the recommended maximum cable loss for antenna cabling is 0.5 dB.
- To ensure best thermal performance, mounting holes must be used to attach (ground) the device to the main PCB ground or a metal chassis.

Note: If the antenna connection is shorted or open, the modem will not sustain permanent damage.

Shielding

The module is fully shielded to protect against EMI and the shield must not be removed.

Antenna and Cabling

When selecting the antenna and cable, it is critical to RF performance to match antenna gain and cable loss.

Note: For detailed electrical performance criteria, see Appendix A: Antenna Specification on page 51.

Choosing the Correct Antenna and Cabling

When matching antennas and cabling:
- The antenna (and associated circuitry) should have a nominal impedance of 50 Ω with a return loss of better than 10 dB across each frequency band of operation.
- The system gain value affects both radiated power *and* regulatory (FCC, IC, CE, etc.) test results.

Designing Custom Antennas

Consider the following points when designing custom antennas:
- A skilled RF engineer should do the development to ensure that the RF performance is maintained.
- If both CDMA and UMTS modules will be installed in the same platform, you may want to develop separate antennas for maximum performance.

Determining the Antenna's Location

When deciding where to put the antennas:
- Antenna location may affect RF performance. Although the module is shielded to prevent interference in most applications, the placement of the antenna is still very important—if the host device is insufficiently shielded, high levels of broadband or spurious noise can degrade the module's performance.
- Connecting cables between the module and the antenna must have 50 Ω impedance. If the impedance of the module is mismatched, RF performance is reduced significantly.
- Antenna cables should be routed, if possible, away from noise sources (switching power supplies, LCD assemblies, etc.). If the cables are near the noise sources, the noise may be coupled into the RF cable and into the antenna. See Interference From Other Wireless Devices on page 31.

Disabling the Diversity Antenna

Certification testing of a device with an integrated MC7421 may require the module's main and diversity antennas to be tested separately.

To facilitate this testing, receive diversity can be enabled/disabled using AT commands:
- !RXDEN—Used to enable/disable diversity for single-cell call (no carrier aggregation).
- !LTERXCONTROL—Used to enable/disable paths (in carrier aggregation scenarios) after a call is set up.

> **Important:** *LTE networks expect modules to have more than one antenna enabled for proper operation. Therefore, customers must not commercially deploy their systems with the diversity antenna disabled.*

For details, see AirPrime EM74xx/MC74xx AT Command Reference (Doc# 4117727).

Note: A diversity antenna is used to improve connection quality and reliability through redundancy. Because two antennas may experience difference interference effects (signal distortion, delay, etc.), when one antenna receives a degraded signal, the other may not be similarly affected.

Ground Connection

When connecting the module to system ground:
- Prevent noise leakage by establishing a very good ground connection to the module through the host connector.
- Connect to system ground using the two mounting holes at the top of the module (shown in Figure 3-1 on page 29).
- Minimize ground noise leakage into the RF.
  Depending on the host board design, noise could *potentially* be coupled to the module from the host board. This is mainly an issue for host designs that have signals traveling along the length of the module, or circuitry operating at both ends of the module interconnects.

Interference and Sensitivity

Several interference sources can affect the module's RF performance (RF desense). Common sources include power supply noise and device-generated RF.

RF desense can be addressed through a combination of mitigation techniques (Methods to Mitigate Decreased Rx Performance on page 32) and radiated sensitivity measurement (Radiated Sensitivity Measurement on page 33).

Note: The MC7421 is based on ZIF (Zero Intermediate Frequency) technologies. When performing EMC (Electromagnetic Compatibility) tests, there are no IF (Intermediate Frequency) components from the module to consider.

Interference From Other Wireless Devices

Wireless devices operating inside the host device can cause interference that affects the module.

To determine the most suitable locations for antennas on your host device, evaluate each wireless device's radio system, considering the following:
- Any harmonics, sub-harmonics, or cross-products of signals generated by wireless devices that fall in the module's Rx range may cause spurious response, resulting in decreased Rx performance.

- The Tx power and corresponding broadband noise of other wireless devices may overload or increase the noise floor of the module's receiver, resulting in Rx desense.

The severity of this interference depends on the closeness of the other antennas to the module's antenna. To determine suitable locations for each wireless device's antenna, thoroughly evaluate your host device's design.

Host-generated RF Interference

All electronic computing devices generate RF interference that can negatively affect the receive sensitivity of the module.

Proximity of host electronics to the antenna in wireless devices can contribute to decreased Rx performance. Components that are most likely to cause this include:
- Microprocessor and memory
- Display panel and display drivers
- Switching-mode power supplies

Device-generated RF Interference

The module can cause interference with other devices. Wireless devices such as AirPrime embedded modules transmit in bursts (pulse transients) for set durations (RF burst frequencies). Hearing aids and speakers convert these burst frequencies into audible frequencies, resulting in audible noise.

Methods to Mitigate Decreased Rx Performance

It is important to investigate sources of localized interference early in the design cycle. To reduce the effect of device-generated RF on Rx performance:
- Put the antenna as far as possible from sources of interference. The drawback is that the module may be less convenient to use.
- Shield the host device. The module itself is well shielded to avoid external inter-ference. However, the antenna cannot be shielded for obvious reasons. In most instances, it is necessary to employ shielding on the components of the host device (such as the main processor and parallel bus) that have the highest RF emissions.
- Filter out unwanted high-order harmonic energy by using discrete filtering on low frequency lines.
- Form shielding layers around high-speed clock traces by using multi-layer PCBs.
- Route antenna cables away from noise sources.

Radiated Spurious Emissions (RSE)

When designing an antenna for use with AirPrime embedded modules, the host device with an AirPrime embedded module must satisfy any applicable standards/local regulatory bodies for radiated spurious emission (RSE) for receive-only mode and for transmit mode (transmitter is operating).

Note that antenna impedance affects radiated emissions, which must be compared against the conducted 50-ohm emissions baseline. (AirPrime embedded modules meet the 50-ohm conducted emissions requirement.)

Radiated Sensitivity Measurement

A wireless host device contains many noise sources that contribute to a reduction in Rx performance.

To determine the extent of any receiver performance desensitization due to self-generated noise in the host device, over-the-air (OTA) or radiated testing is required. This testing can be performed by Sierra Wireless or you can use your own OTA test chamber for in-house testing.

Sierra Wireless' Sensitivity Testing and Desensitization Investigation

Although AirPrime embedded modules are designed to meet network operator requirements for receiver performance, they are still susceptible to various performance inhibitors.

As part of the Engineering Services package, Sierra Wireless offers modem OTA sensitivity testing and desensitization (desense) investigation. For more information, contact your account manager or the Sales Desk (see Contact Information on page 3).

Note: Sierra Wireless has the capability to measure TIS (Total Isotropic Sensitivity) and TRP (Total Radiated Power) according to CTIA's published test procedure.

Sensitivity vs. Frequency

For UMTS bands, sensitivity is defined as the input power level in dBm that produces a BER (Bit Error Rate) of 0.1%. Sensitivity should be measured at all UMTS frequencies across each band.

For LTE bands, sensitivity is defined as the RF level at which throughput is 95% of maximum.

Supported Frequencies

The MC7421 supports:
* Multiple-band LTE—See Table 3-1 on page 34 (supported bands) and Table 3-2 on page 34 (LTE bandwidth support).
* LTE Advanced carrier aggregation—See Table 1-2 on page 10 and Table 1-3 on page 11 for details..
* Multiple-band WCDMA/HSPA/HSPA+/DC-HSPA+—See Table 3-3 on page 35.
* Multiple-band WCDMA receive diversity
* GPS, GLONASS, BeiDou, Galileo—See Table 3-7 on page 36.
* Inter-RAT and inter-frequency cell reselection and handover between supported frequency bands

Table 3-1: LTE Frequency Bands

Band	Frequency (Tx)	Frequency (Rx)
B1	1920–1980 MHz	2110–2170 MHz
B3	1710–1785	1805–1880 MHz
B7	2500–2570 MHz	2620–2690 MHz
B8	880–915 MHz	925–960 MHz
B20	832–862 MHz	791–821 MHz
B28	703–748 MHz	758–803 MHz
B32	n/a	1452–1496 MHz
B38	2570–2620 MHz (TDD)	
B40	2300–2400 MHz (TDD)	
B41	2496–2690 MHz (TDD)	
B42	3400–3600 MHz (TDD)	
B43	3600–3800 MHz (TDD)	

Table 3-2: LTE Bandwidth Support[a]

Band	1.4 MHz	3 MHz	5 MHz	10 MHz	15 MHz	20 MHz
B1	✘	✘	✔	✔	✔	✔
B3	✔	✔	✔	✔	✔[b]	✔[b]
B7	✘	✘	✔	✔	✔[c]	✔[b,c]
B8	✔	✔	✔	✔[b]	✘	✘
B20	✘	✘	✔	✔[b]	✔[b]	✔[b]
B28	✘	✔	✔	✔[b]	✔[b]	✔[b,d]
B32	✘	✘	✔	✔	✔	✔
B38	✘	✘	✔	✔	✔[c]	✔[c]
B40	✘	✘	✔	✔	✔	✔
B41	✘	✘	✔	✔	✔	✔
B42	✘	✘	✔	✔	✔	✔
B43	✘	✘	✔	✔	✔	✔

a. Table contents are derived from 3GPP TS 36.521-1 v12.6.0, table 5.4.2.1-1.
b. Bandwidth for which a relaxation of the specified UE receiver sensitivity requirement (Clause 7.3 of 3GPP TS 36.521-1 v12.6.0) is allowed.
c. Bandwidth for which uplink transmission bandwidth can be restricted by the network for some channel assignments in FDD/TDD co-existence scenarios in order to meet unwanted emissions requirements (Clause 6.6.3.2 of 3GPP TS 36.521-1 v12.6.0).
d. For 20 MHz bandwidth, the minimum requirements are specified for E-UTRA UL carrier frequencies confined to either 713–723 MHz or 728–738 MHz.

Table 3-3: WCDMA Frequency Bands Support

Band	Frequency (Tx)	Frequency (Rx)
Band 1	1920–1980 MHz	2110–2170 MHz
Band 5	824–849 MHz	869–894 MHz
Band 8	880–915 MHz	925–960 MHz

Conducted Rx Sensitivity / Tx Power

Note: Values in the following tables are preliminary, pending transceiver matching/testing.

Table 3-4: Conducted Rx (Receive) Sensitivity — LTE Bands[a]

LTE bands		Conducted Rx sensitivity (dBm)			
		Primary (Typ)	Secondary (Typ)	SIMO (Typ)	SIMO[b] (Worst case)
B1	Full RB on downlink; BW: 10 MHz[c]	TBD	TBD	TBD	-96.3
B3		TBD	TBD	TBD	-93.3
B7		TBD	TBD	TBD	-94.3
B8		TBD	TBD	TBD	-93.3
B20		TBD	TBD	TBD	-93.3
B28		TBD	TBD	TBD	-94.8
B32		TBD	TBD	TBD	-96.3
B38		TBD	TBD	TBD	-96.3
B40		TBD	TBD	TBD	-96.3
B41		TBD	TBD	TBD	-94.3
B42		TBD	TBD	TBD	-95.0
B43		TBD	TBD	TBD	-95.0

a. Preliminary values, pending validation
b. Per 3GPP specification
c. Sensitivity values scale with bandwidth:
   x_MHz_Sensitivity = 10_MHz_Sensitivity - 10*log(10 MHz/x_MHz)
   Note: Bandwidth support is dependent on firmware version.

Table 3-5: Conducted Rx (Receive) Sensitivity — UMTS Bands[a]

UMTS bands		Conducted Rx sensitivity (dBm)		
		Primary (Typical)	Secondary (Typical)	Primary/Secondary (Worst case)[b]
Band 1	0.1% BER 12.2 kbps	TBD	TBD	-106.7
Band 5		TBD	TBD	-104.7
Band 8		TBD	TBD	-103.7

a. Preliminary values, pending validation
b. Per 3GPP specification

Table 3-6: Conducted Tx (Transmit) Power Tolerances[a]

Bands	Conducted Tx power	Notes
LTE		
LTE bands 1,3,7,8,20,28,32,38,40,41,42,43	TBD dBm $\pm$ TBD dB	
UMTS		
Band 1 (IMT 2100 12.2 kbps) Band 5 (UMTS 850 12.2 kbps) Band 8 (UMTS 900 12.2 kbps)	+TBD dBm $\pm$ TBD dB	Connectorized (Class 3)

a. Preliminary values, pending validation

GNSS Specifications

Note: For detailed electrical performance criteria, see Recommended GNSS Antenna Specifications on page 53.

Table 3-7: GNSS Specifications[a]

Parameter/feature	Description
Satellite channels	Maximum 30 channels (16 GPS, 14 GLONASS), simultaneous tracking
Protocols	NMEA 0183 V3.0
Acquisition time[b]	Hot start: 1 s Warm start: 29 s Cold start: 32 s
Accuracy	Horizontal: < 2 m (50%); < 5 m (90%) Altitude: < 4 m (50%); < 8 m (90%) Velocity: < 0.2 m/s

Table 3-7: GNSS Specifications[a] (Continued)

Parameter/feature	Description
Sensitivity	Tracking[c]: -160 dBm Acquisition[d] (Assisted): -158 dBm Acquisition (Standalone): -145 dBm
Operational limits	Altitude <6000 m or velocity <100 m/s (Either limit may be exceeded, but not both.)

a. Preliminary values, pending validation
b. Acquisition times measured with signal strength = -135 dBm
c. Tracking sensitivity is the lowest GNSS signal level for which the device can still detect an in-view satellite 50% of the time when in sequential tracking mode.
d. Acquisition sensitivity is the lowest GNSS signal level for which the device can still detect an in-view satellite 50% of the time.

The module includes an internal GNSS LNA.

4: Power

Power Consumption

Power consumption measurements in the tables below are for the MC7421 Mini Card module connected to the host PC via USB.

The module does not have its own power source and depends on the host device for power. For a description of input voltage requirements, see Power Supply on page 20.

Table 4-1: Averaged Standby DC Power Consumption[a]

Signal	Description	Bands[b]	Current			Notes / configuration
			Typ	Max[c]	Unit	
VCC	**Standby current consumption (Sleep mode activated[d])**					
	LTE	LTE bands	TBD	TBD	mA	DRX cycle = 8 (2.56 s)
	HSPA / WCDMA	UMTS bands	TBD	TBD	mA	DRX cycle = 8 (2.56 s)
	Standby current consumption[e] (Sleep mode deactivated[d])					
	LTE	LTE bands	TBD	TBD	mA	DRX cycle = 8 (2.56 s)
	HSPA / WCDMA	UMTS bands	TBD	TBD	mA	DRX cycle = 8 (2.56 s)
	Low Power Mode (LPM)/Offline Mode[e] (Sleep mode activated[d])					
	RF disabled, but module is operational		TBD	TBD	mA	
	Low Power Mode (LPM)/Offline Mode[e] (Sleep mode deactivated[d])					
	RF disabled, but module is operational		TBD	TBD	mA	
	Leakage current					
	Module powered off— Full_Card_Power_Off# is Low, and VCC is supplied		TBD	TBD	µA	

a.   Preliminary values, pending validation
b.   For supported bands, see Table 3-1, LTE Frequency Bands, on page 34 and Table 3-3, WCDMA Frequency Bands Support, on page 35.
c.   Measured at 25ºC/nominal 3.3 V voltage.
d.   Assumes USB bus is fully suspended during measurements
e.   LPM and standby power consumption will increase when LEDs are enabled. To reduce power consumption, configure LEDs to remain off while in standby and LPM modes.

Table 4-2: Averaged Call Mode DC Power Consumption[a]

Description	Tx power	Current[b]		Notes
		Typ	Unit	
LTE	0 dBm	TBD	mA	CA 300/50 Mbps, 20 MHz+20 MHz BW
		TBD	mA	CA 100/50 Mbps, 10 MHz+10 MHz BW
		TBD	mA	150/50 Mbps, 20 MHz BW
	20 dBm	TBD	mA	CA 300/50 Mbps, 20 MHz+20 MHz BW
		TBD	mA	CA 100/50 Mbps, 10 MHz+10 MHz BW
		TBD	mA	150/50 Mbps, 20 MHz BW
	23 dBm	TBD	mA	CA 300/50 Mbps, 20 MHz+20 MHz BW
		TBD	mA	CA 100/50 Mbps, 10 MHz+10 MHz BW
		TBD	mA	150/50 Mbps, 20 MHz BW
DC-HSPA/HSPA	0 dBm	TBD	mA	All speeds
	20 dBm	TBD	mA	All speeds
	23 dBm	TBD	mA	Worst case
Peak current (averaged over 100 μs)		TBD	A	All LTE/WCDMA bands

a. Preliminary values, pending validation
b. Measured at 25ºC/nominal 3.3 V voltage

Table 4-3: Miscellaneous DC Power Consumption[a]

Signal	Description	Current/Voltage			Unit	Notes/configuration
		Min	Typ	Max		
VCC	USB active current	—	TBD	TBD	mA	High speed USB connection, C_L = 50 pF on D+ and D- signals
	Inrush current	—	TBD	TBD	A	• Assumes power supply turn on time > 100µs • Dependent on host power supply rise time.
	Maximum current	—	—	TBD	A	• Across all bands, all temperature ranges • 3.3 V supply
GNSS Signal connector	Active bias on GNSS port	—	—	TBD	mA	Voltage applied to the GNSS antenna to power electronics inside the antenna (GNSS RF connector in Figure 3-1 on page 29).
		TBD	TBD	TBD	V	

a. Preliminary values, pending validation

Module Power States

The module has four power states, as described in Table 4-4.

Table 4-4: Module Power States

State	Details	Host is powered	Module is powered	USB interface active	RF enabled

Normal (Default state)	• Module is active
	• Default state when VCC is first applied in the absence of W_DISABLE_N control
	• Module is capable of placing/receiving calls, or establishing data connections on the wireless network
	• Current consumption is affected by several factors, including:
	  • Radio band being used
	  • Transmit power
	  • Receive gain settings
	  • Data rate
	  • Number of active Tx time slots
		✔	✔	✔	✔

Low power ('Airplane mode')	• Module is active
	• Module enters this state:
	  • Under host interface control:
	    · Host issues AT+CFUN=0 (*[1] AT Command Set for User Equipment (UE) (Release 6) (Doc# 3GPP TS 27.007)*)), or
	    · Host issues AT!PCOFFEN=0 (configures the modem to enter low power mode when W_DISABLE_N is asserted), and then asserts W_DISABLE_N
	  • Automatically, when critical temperature or voltage trigger limits have been reached
		✔	✔	✔	✘

Sleep	• Normal state of module between calls or data connections • Module cycles between wake (polling the network) and sleep, at network provider-determined interval.	✔	✔	✘	✘
Disconnected	• Host power source is disconnected from the module and all voltages associated with the module are at 0 V.	✘	✘	✘	✘

Power State Transitions

The module uses state machines to monitor supply voltage and operating temperature, and notifies the host when critical threshold limits are exceeded. (See Table 4-5 for trigger details and Figure 4-1 for state machine behavior.)

Power state transitions may occur:
- Automatically, when critical supply voltage or module temperature trigger levels are encountered.
- Under host control, using available AT commands in response to user choices (for example, opting to switch to airplane mode) or operating conditions.

Table 4-5: Power State Transition Trigger Levels

Transition	Voltage		Temperature[a]		Notes
	Trigger	V[b]	Trigger	°C	
Normal to Low Power	VOLT_HI_CRIT	3.8	TEMP_LO_CRIT	-45	• RF activity suspended
	VOLT_LO_CRIT	2.9	TEMP_HI_CRIT	93	
Low Power to Normal	VOLT_HI_NORM	3.5	TEMP_NORM_LO	-30	• RF activity resumed
Low Power to Normal *or* Remain in Normal (Remove warnings)	VOLT_LO_NORM	3.05	TEMP_HI_NORM	70	
Normal (Issue warning)	VOLT_LO_WARN	2.95	TEMP_HI_WARN	80	• In the TEMP_HI_WARN state, the module may have reduced performance (Class B temp. range).
Power off/on (Host-initiated)	-	-	-	-	• Power off recommended when supply voltage or module operating temperature is critically low or high.

a. Module-reported temperatures at the printed circuit board.
b. Supply voltage—3.3V
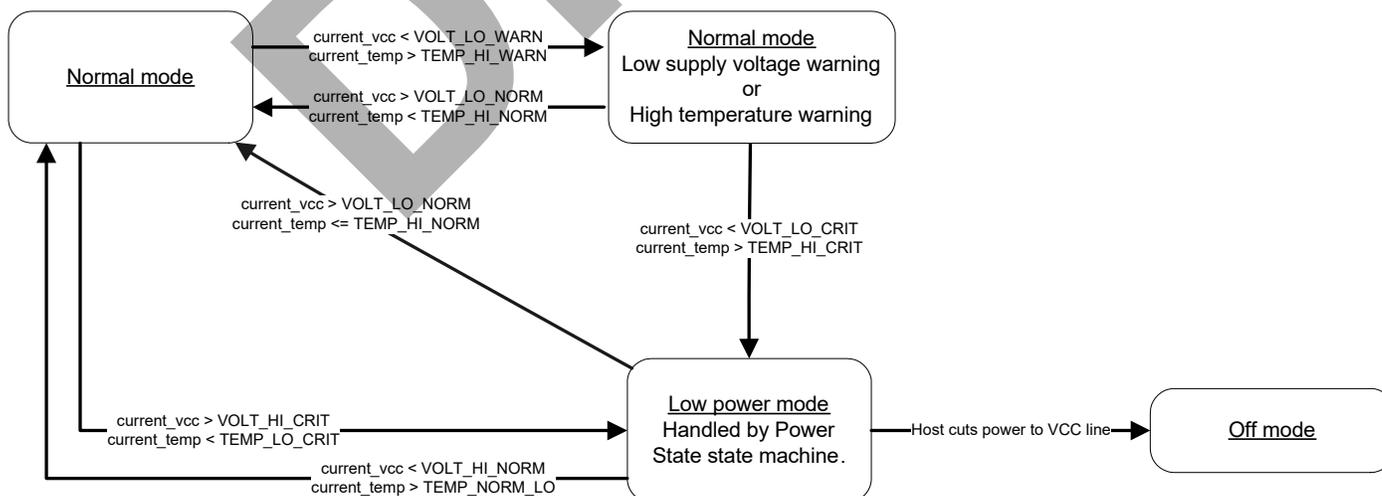
Figure 4-1: Voltage/Temperature Monitoring State Machines

Power Interface

Power Ramp-up

On initial power up, inrush current depends on the power supply rise time—turn on time >100 µs is required for < 3A inrush current.

The supply voltage must remain within specified tolerances while this is occurring.

Power-On/Off Timing

Figure 4-2 describes the timing sequence for powering the module on and off.

Note: Before reaching the "Active" state, signals on the host port are considered to be undefined and signal transitions may occur. This undefined state also applies when the module is in reset mode, during a firmware update, or during the Power-off sequence. The host must consider these undefined signal activities when designing the module interface.

Note: The host should not drive any signals to the module until the power-on sequence is complete.
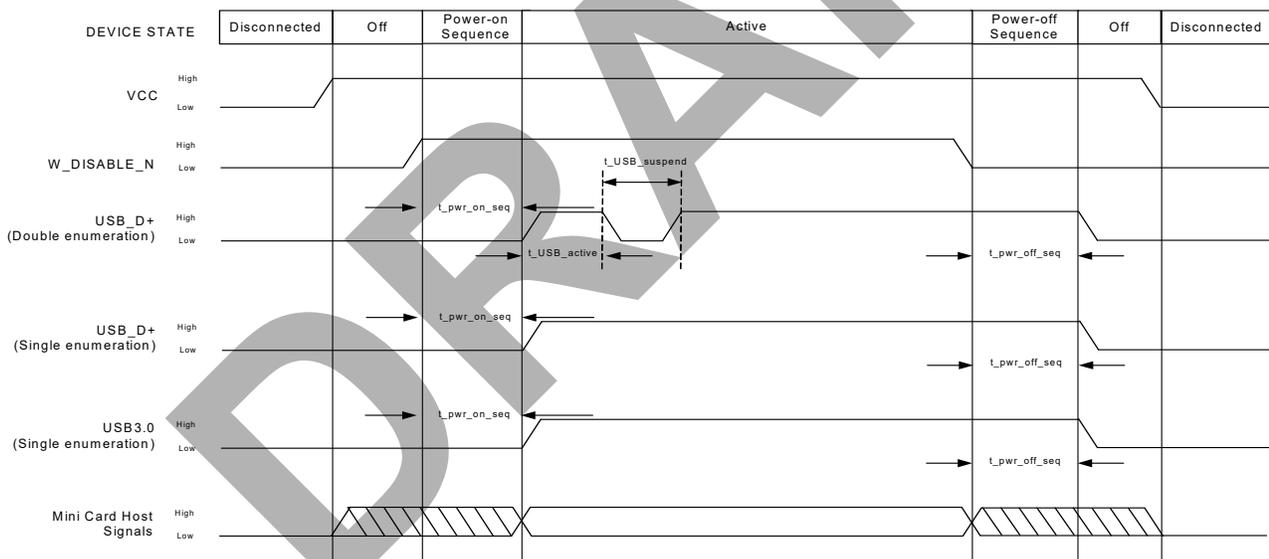
Figure 4-2: Signal Timing (W_DISABLE_N, and USB Enumeration)

Table 4-6: USB 2.0 Power-On/Off Timing Parameters (Double Enumeration)

Parameter	Typical (s)	Maximum (s)
t_pwr_on_seq	0.8	0.9
t_USB_active	0.12	0.2
t_USB_suspend	8.5	11
t_pwr_off_seq	21.4	25

Table 4-7: USB 2.0 Power-On/Off Timing Parameters (Single Enumeration)

Parameter	Typical (s)	Maximum (s)
t_pwr_on_seq	8.7	11
t_pwr_off_seq	21.4	25

Table 4-8: USB 3.0 Power-On/Off Timing Parameters (Single Enumeration)

Parameter	Typical (s)	Maximum (s)
t_pwr_on_seq	8.6	11
t_pwr_off_seq	21.5	25

USB Enumeration

The unit supports single and double USB enumeration with the host:
- Single enumeration:
  - Enumeration starts within maximum t_pwr_on_seq seconds of power-on.
- Double enumeration—As shown in :
  - First enumeration starts within t_pwr_on_seq seconds of power-on (while USB_D+ is high)
  - Second enumeration starts after t_USB_suspend (when USB_D+ goes high again)

Required Shutdown Sequence

Warning: *To avoid causing issues with the file system, follow this shutdown sequence.*

---

1. Enable the shutdown feature with AT!PCOFFEN=0.
2. Assert W_DISABLE_N.
3. Wait for at least t_pwr_off_seq.
4. Remove power.

Power Supply Noise

Noise in the power supply can lead to noise in the RF signal.

The power supply ripple limit for the module is no more than 100 mVp-p 1 Hz to 100 kHz. This limit includes voltage ripple due to transmitter burst activity.

Additional decoupling capacitors can be added to the main VCC line to filter noise into the device.

SED (Smart Error Detection)

The module uses a form of SED to track premature modem resets.
- Module tracks consecutive resets occurring soon after power-on.
- After a sixth consecutive reset, the module waits in boot-and-hold mode for a firmware download to resolve the power-cycle problem.

Tx Power Control

The module's Tx power limit may be controlled using either SAR backoff AT commands (defined in *[2] AirPrime EM74xx/MC74xx AT Command Reference (Doc# 4117727)*), or the DPR (Dynamic power control) signal. Use the GPIOSARENABLE parameter for !CUSTOM to choose the method:

- AT commands:
  - !SARSTATED—Set (or report) the default SAR backoff state that the device uses when it powers up. This setting persists across power cycles and overrides any PRI setting.
  - !SARSTATE—Set (or report) the current SAR backoff state (override the default state). This change in state is non-persistent across power cycles.
  - !SARBACKOFF—Set (or report) the maximum Tx power limit for a specific band/ technology/state combination.
- Dynamic power control—The module's firmware monitors DPR (pin 46) and adjusts the RF Tx power appropriately, as detailed in Table 4-9 on page 44. (This state change is equivalent to using the !SARSTATE AT command.)

Note: A customization is available to invert the DPR logic. (e.g. DPR low = No SAR backoff)

Table 4-9: Dynamic Power Control of SAR Backoff State

DPR	SAR backoff state
High[a]	No SAR backoff
Low	Backoff 1

a. DPR is pulled high by default.

Note: The host can implement an open collector drive for the DPR pin (if a 1.8 V-compatible drive is not available.)

>> 5: Software Interface

Support Tools

The MC7421 is compatible with the following support tools from Sierra Wireless and authorized third parties:
- Firmware update utilities from Sierra Wireless
- Sierra Wireless Logger
- QXDM from QUALCOMM
- QUALCOMM Product Support Tool (QPST)
- Windows and Linux SDK (including APIs and drivers)

Host Interface

The device supports the following protocols for modem communication:
- MBIM (Mobile Broadband Interface Model)
- Qualcomm QMI interface. (Please contact your Sierra Wireless account representative for QMI interface documentation.)

6: Mechanical and Environmental Specifications

The MC7421 module complies with the mechanical and environmental specifications in Table 6-1. Final product conformance to these specifications depends on the OEM device implementation.

Table 6-1: Mechanical and Environmental Specifications[a]

	Mode	Details
Ambient temperature	Operational Class A	-30ºC to +70ºC – 3GPP compliant
	Operational Class B	-40ºC to +85ºC, with appropriate heatsinking – non-3GPP compliant (reduced operating parameters required)
	Non-operational	-40ºC to +85ºC, 96 hours (from MIL-STD 202 Method 108)
Relative humidity	Non-operational	85ºC, 85% relative humidity for 48 hours (non-condensing)
Vibration	Non-operational	Random vibration, 10 to 2000 Hz, 0.1 g^2/Hz to 0.0005 g^2/Hz, in each of three mutually perpendicular axes. Test duration of 60 minutes for each axis, for a total test time of three hours.
Shock	Non-operational	Half sine shock, 11 ms, 30 g, 8x each axis. Half sine shock, 6 ms, 100 g, 3x each axis.
Drop	Non-operational	1 m on concrete on each of six faces, two times (module only).
(Electrostatic discharge (See Electrostatic Discharge (ESD) on page 47.)	Operational	The RF port (antenna launch and RF connector) complies with the IEC 61000-4-2 standard: • Electrostatic Discharge Immunity: Test: Level3 Contact Discharge: ±6 kV Air Discharge: ±8 kV
	Non-operational	The host connector Interface complies with the following standard only: • minimum ±500 V Human Body Model (JESD22-A114-B)
Thermal considerations		See Thermal Considerations on page 47.
Form factor		PCI-Express Mini Card shielded with metal and metalized fabric (F2 specification)
Dimensions		Length: 51 mm Width: 30 mm Thickness: 3.6 mm Weight: TBD g

a. Specifications and associated standards to be confirmed.

Electrostatic Discharge (ESD)

The OEM is responsible for ensuring that the Mini Card host interface pins are not exposed to ESD during handling or normal operation. (See Table 6-1 on page 46 for specifications.)

ESD protection is highly recommended for the SIM connector at the point where the contacts are exposed, and for any other signals from the host interface that would be subjected to ESD by the user of the product. (The device includes ESD protection on the antenna.)

Thermal Considerations

Embedded modules can generate significant amounts of heat that must be dissipated in the host device for safety and performance reasons.
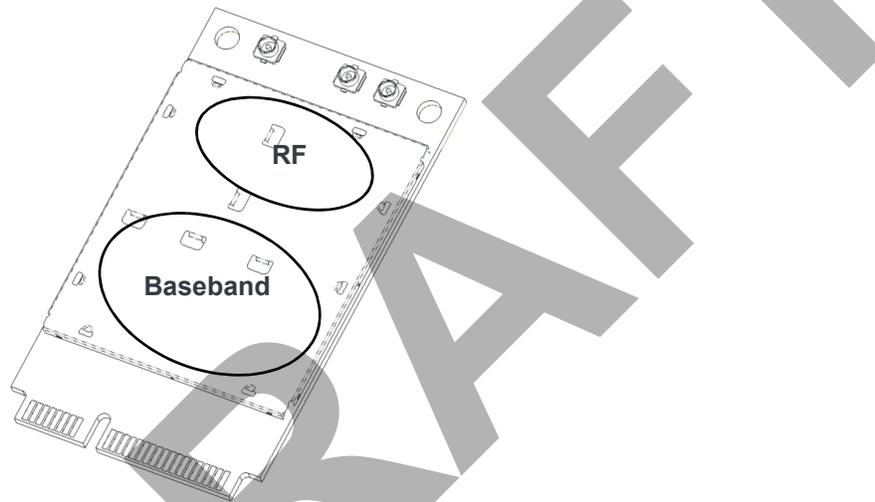
Figure 6-1: Shield locations requiring heat dissipation (Top view)

The amount of thermal dissipation required depends on:
• Supply voltage—Maximum power dissipation for the module can be up to 3.5 W at voltage supply limits.
• Usage—Typical power dissipation values depend on the location within the host product, throughput, amount of data transferred, etc.

Specific areas requiring heat dissipation are shown in Figure 6-1:
• RF—Bottom face of module near RF connectors. Likely to be the hottest area.
• Baseband—Bottom face of module, below the baseband area.
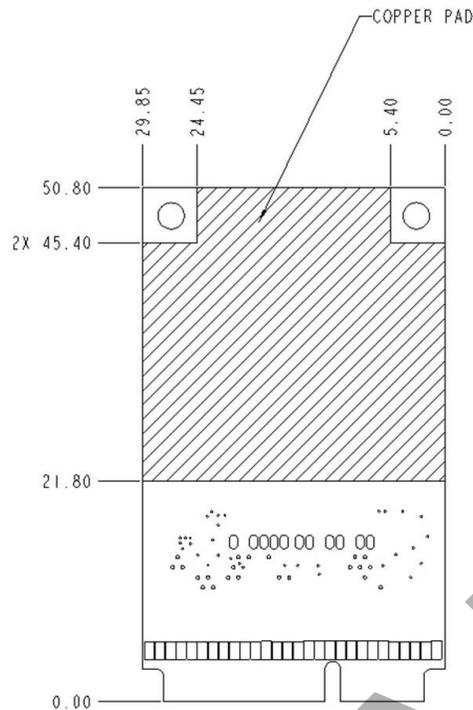
Figure 6-2: Copper Pad Location on Bottom Side of Module

To enhance heat dissipation:
- It is recommended to add a heat sink that mounts the module to the main PCB or metal chassis (a thermal compound or pads must be used between the module and the heat sink).
- Maximize airflow over/around the module.
- Locate the module away from other hot components.
- Module mounting holes must be used to attach (ground) the device to the main PCB ground or a metal chassis.
- You may also need active cooling to pull heat away from the module.

Note: Adequate dissipation of heat is necessary to ensure that the module functions properly.

Module Integration Testing

When testing your integration design:
- Test to your worst case operating environment conditions (temperature and voltage)
- Test using worst case operation (transmitter on 100% duty cycle, maximum power)
- Monitor temperature on the underside of the module. Attach thermocouples to the areas indicated in Figure 6-1 on page 47 (Baseband, RF).
- Monitor the module's internal temperature using **AT!PCTEMP**. (See *[2] AirPrime EM74xx/MC74xx AT Command Reference (Doc# 4117727)*.)

Note: Make sure that your system design provides sufficient cooling for the module—proper mounting, heat sinks, and active cooling may be required, depending on the integrated application. The internal module temperature (reported by AT!PCTEMP) must be kept to <90°C when integrated to prevent damage to the module's components. For best performance, keep the internal module temperature below 80°C.

(For acceptance, certification, quality, and production (including RF) test suggestions, see .)

7: Regulatory Compliance and Industry Certifications

This module is designed to meet, and upon commercial release, will meet the requirements of the following regulatory bodies and regulations, where applicable:
- The National Communications Commission (NCC) of Taiwan, Republic of China
- Radio Equipment Directive (RED) of the European Union

The MC7421 Mini Card complies with the mandatory requirements described in the following standards. The exact set of requirements supported is network operator-dependent.

Table 7-1: Standards Compliance

Technology	Standards
LTE	• 3GPP Release 11[a]
UMTS	• 3GPP Release 9

a. Some auxiliary functions support Release 12 or Release 13.

Upon commercial release, the following industry certifications will have been obtained, where applicable:
- GCF

Additional certifications and details on specific country approvals may be obtained upon customer request—contact your Sierra Wireless account representative for details.

Additional testing and certification may be required for the end product with an embedded MC7421 module and are the responsibility of the OEM. Sierra Wireless offers professional services-based assistance to OEMs with the testing and certification process, if required.

A: Antenna Specification

This appendix describes recommended electrical performance criteria for main path, diversity path, and GNSS antennas used with AirPrime embedded modules.

The performance specifications described in this section are valid while antennas are mounted in the host device with antenna feed cables routed in their final application configuration.

*Note: Antennas should be designed **before** the industrial design is finished to make sure that the best antennas can be developed.*

Recommended Main/Diversity Antenna Specifications

Table A-1: Antenna Requirements [a]

Parameter	Requirements	Comments
Antenna system	(LTE) External multi-band 2x2 MIMO antenna system (Ant1/Ant2)[b] (3G) External multi-band antenna system with diversity (Ant1/Ant2)[c]	If Ant2 includes GNSS, then it must also satisfy requirements in Table A-2 on page 53.
Operating bands—Antenna 1	All supporting Tx and Rx frequency bands.	
Operating bands—Antenna 2	All supporting Rx frequency bands, plus GNSS frequency bands if Antenna 2 is used in shared Diversity/MIMO/GNSS mode.	
VSWR of Ant1 and Ant2	• < 2:1 (recommended) • < 3:1 (worst case)	On all bands including band edges
Total radiated efficiency of Ant1 and Ant2	> 50% on all bands	• Measured at the RF connector. • Includes mismatch losses, losses in the matching circuit, and antenna losses, excluding cable loss. • Sierra Wireless recommends using antenna efficiency as the primary parameter for evaluating the antenna system. Peak gain is not a good indication of antenna performance when integrated with a host device (the antenna does not provide omni-directional gain patterns). Peak gain can be affected by antenna size, location, design type, etc.—the antenna gain patterns remain fixed unless one or more of these parameters change.

Table A-1: Antenna Requirements (Continued)[a]

Parameter	Requirements	Comments
Radiation patterns of Ant1 and Ant2	Nominally Omni-directional radiation pattern in azimuth plane.	
Envelope correlation coefficient between Ant1 and Ant2	• < 0.5 on Rx bands below 960 MHz • < 0.2 on Rx bands above 1.4 GHz	
Mean Effective Gain of Ant1 and Ant2 (MEG1, MEG2)	≥ -3 dBi	
Ant1 and Ant2 Mean Effective Gain Imbalance I MEG1 / MEG2 I	< 2 dB for MIMO operation < 6 dB for diversity operation	
Isolation between Ant1 and Ant2 (S21)	> 10 dB	• If antennas can be moved, test all positions for both antennas. • Make sure all other wireless devices (Bluetooth or WLAN antennas, etc.) are turned OFF to avoid interference.
Power handling	• > 1 W on high bands	• Measure power endurance over 4 hours (estimated talk time) using a 2 W CW signal—set the CW test signal frequency to the middle of the PCS Tx band (1880 MHz for PCS). • Visually inspect device to ensure there is no damage to the antenna structure and matching components. • VSWR/TIS/TRP measurements taken before and after this test must show similar results.

a. These worst-case VSWR figures for the transmitter bands may not guarantee RSE levels to be within regulatory limits. The device alone meets all regulatory emissions limits when tested into a cabled (conducted) 50 ohm system. With antenna designs with up to 2.5:1 VSWR or worse, the radiated emissions could exceed limits. The antenna system may need to be tuned in order to meet the RSE limits as the complex match between the module and antenna can cause unwanted levels of emissions. Tuning may include antenna pattern changes, phase/delay adjustment, passive component matching. Examples of the application test limits would be included in FCC Part 22, Part 24 and Part 27, test case 4.2.2 for WCDMA (ETSI EN 301 908-1), where applicable.

b. Ant1—Primary, Ant2—Secondary (Diversity/MIMO/GNSS)

c. Ant1—Primary, Ant2—Secondary (Diversity/GNSS)

Recommended GNSS Antenna Specifications

Table A-2: GNSS Antenna Requirements

Parameter	Requirements	Comments
Frequency range	• Wide-band GNSS: 1560–1606 MHz recommended • Narrow-band GPS: 1575.42 MHz ±2 MHz minimum • Narrow-band Galileo: 1575.42 MHz ±2 MHz minimum • Narrow-band BeiDou: 1561.098 MHz ±2 MHz minimum • Narrow-band GLONASS: 1601.72 MHz ±4.2 MHz minimum	
Field of view (FOV)	• Omni-directional in azimuth • -45° to +90° in elevation	
Polarization (average Gv/Gh)	> 0 dB	Vertical linear polarization is sufficient.
Free space average gain (Gv+Gh) over FOV	> -6 dBi (preferably > -3 dBi)	Gv and Gh are measured and averaged over -45° to +90° in elevation, and ±180° in azimuth.
Gain	• Maximum gain and uniform coverage in the high elevation angle and zenith. • Gain in azimuth plane is not desired.	
Average 3D gain	> -5 dBi	
Isolation between GNSS and Ant1	> 10 dB in all uplink bands	
Typical VSWR	< 2.5:1	
Polarization	Any other than LHCP (left-hand circular polarized) is acceptable.	

Antenna Tests

The following guidelines apply to the requirements described in and :

- Perform electrical measurements at room temperature (+20°C to +26°C) unless otherwise specified
- For main and diversity path antennas, make sure the antennas (including contact device, coaxial cable, connectors, and matching circuit with no more than six components, if required) have nominal impedances of 50 Ω across supported frequency bands.
- All tests (except isolation/correlation coefficient)—Test the main or diversity antenna with the other antenna terminated.
- Any metallic part of the antenna system that is exposed to the outside environment needs to meet the electrostatic discharge tests per IEC61000-4-2 (conducted discharge +8kV).

- The functional requirements of the antenna system are tested and verified while the embedded module's antenna is integrated in the host device.

Note: Additional testing, including active performance tests, mechanical, and accelerated life tests can be discussed with Sierra Wireless' engineering services. Contact your Sierra Wireless representative for assistance.

DRAFT

B: Design Checklist

This chapter provides a summary of the design considerations mentioned throughout this guide. This includes items relating to the power interface, RF integration, thermal considerations, cabling issues, and so on.

Note: This is NOT an exhaustive list of design considerations. It is expected that you will employ good design practices and engineering principles in your integration.

Table B-1: Hardware Integration Design Considerations

Suggestion	Section where discussed
Component placement	
Protect the SIM socket so the SIM cannot be removed while the host is powered up.	SIM Implementation on page 24
If an ESD suppressor is not used, allow space on the SIM connector for series resistors in layout. (Up to 100 Ω may be used depending on ESD testing requirements).	SIM Implementation on page 24
Minimize RF cable losses as these affect performance values listed in product specification documents.	RF Connections on page 29
Antennas	
Match the module/antenna coax connections to 50 Ω—mismatched antenna impedance and cable loss negatively affect RF performance.	RF Connections on page 29
If installing CDMA and UMTS modules in the same device, consider using separate antennas for maximum performance.	Antenna and Cabling on page 30
Power	
Make sure the power supply can handle the maximum current specified for the module type.	Power Consumption on page 38
Limit the total impedance of VCC and GND connections to the SIM at the connector to less than 1 Ω (including any trace impedance and lumped element components—inductors, filters, etc.). All other lines must have a trace impedance less than 2 Ω.	SIM Implementation on page 24
Decouple the VCC line close to the SIM socket. The longer the trace length (impedance) from socket to module, the greater the capacitance requirement to meet compliance tests.	SIM Implementation on page 24
PCB signal routing	
USB 2.0/3.0—Route these signals over 90 Ω differential lines on the PCB.	
EMI/ESD	
Investigate sources of localized interference early in the design cycle.	Methods to Mitigate Decreased Rx Performance on page 32
Provide ESD protection for the SIM connector at the exposed contact point (in particular, the CLK, VCC, IO, and RESET lines).	SIM Implementation on page 24

Table B-1: Hardware Integration Design Considerations (Continued)

Suggestion	Section where discussed
Keep very low capacitance traces on the USIM_DATA and USIM_CLK signals.	SIM Implementation on page 24
To minimize noise leakage, establish a very good ground connection between the module and host.	Ground Connection on page 31
Route cables away from noise sources (for example, power supplies, LCD assemblies, etc.).	Methods to Mitigate Decreased Rx Performance on page 32
Shield high RF-emitting components of the host device (for example, main processor, parallel bus, etc.).	Methods to Mitigate Decreased Rx Performance on page 32
Use discrete filtering on low frequency lines to filter out unwanted high-order harmonic energy.	Methods to Mitigate Decreased Rx Performance on page 32
Use multi-layer PCBs to form shielding layers around high-speed clock traces.	Methods to Mitigate Decreased Rx Performance on page 32
Thermal	
Test to worst case operating conditions—temperature, voltage, and operation mode (transmitter on 100% duty cycle, maximum power).	Thermal Considerations on page 47
Use appropriate techniques to reduce module temperatures (for example, airflow, heat sinks, heat-relief tape, module placement, etc.).	Thermal Considerations on page 47
Host/Modem communication	
Make sure the host USB driver supports remote wakeup, resume, and suspend operations, and serial port emulation.	*[4] AirCard/AirPrime USB Driver Developer's Guide (Doc# 2130634)*
When no valid data is being sent, do not send SOF tokens from the host (causes unnecessary power consumption).	*[4] AirCard/AirPrime USB Driver Developer's Guide (Doc# 2130634)*

>> C: Packaging

Sierra Wireless AirPrime Mini Cards are shipped in sealed boxes. The standard packaging (see Figure C-1), contains a single tray with a capacity of 100 modules. (Note that some SKUs may have custom packaging—contact Sierra Wireless for SKU-specific details.)

In the standard packaging, Mini Cards are inserted, system connector first, into the bottom portion (T1) of a two-part tray. all facing the same direction. This allows the top edge of each Mini Card to contact the top of the triangular features in the top portion (T2) of the tray (see Detail A).

The top and bottom portions of the tray snap together at the four connection points.
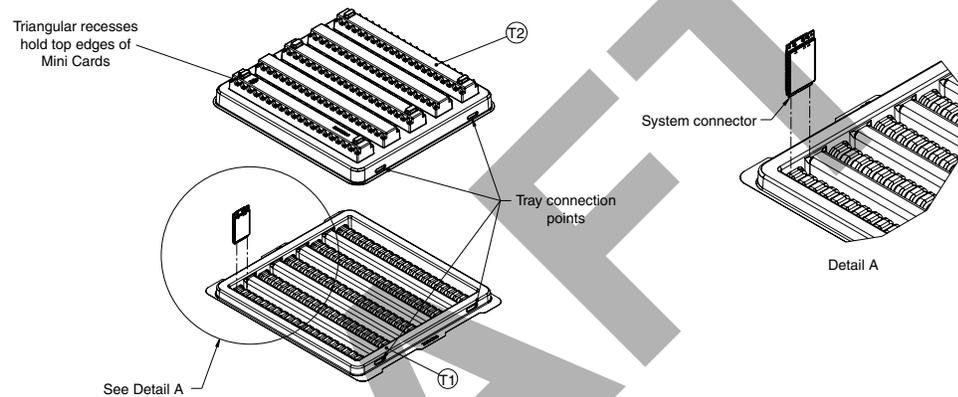
Figure C-1: Device Placement in Module Tray

The tray is placed in a manufacturing box (T2 at the top), sealed with a security tape (P1), and a manufacturing label is placed on the bottom-right corner, above the security tape. (See Figure C-2.)
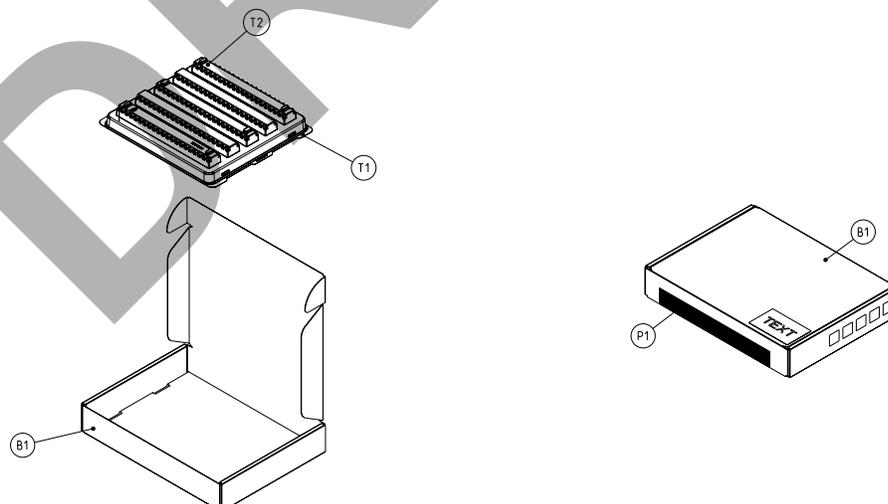
Figure C-2: Shipping Package

>> D: References

This guide deals specifically with hardware integration issues that are unique to AirPrime embedded modules.

Sierra Wireless Documents

The Sierra Wireless documents listed below are available from www.sierrawireless.com. For additional documents describing embedded module design, usage, and integration issues, contact your Sierra Wireless account representative.

Command Documents

[1] AT Command Set for User Equipment (UE) (Release 6) (Doc# 3GPP TS 27.007)

[2] AirPrime EM74xx/MC74xx AT Command Reference (Doc# 4117727)

Other Sierra Documents

[3] PCI Express Mini Card Dev Kit Quick Start Guide (Doc# 2130705)

[4] AirCard/AirPrime USB Driver Developer's Guide (Doc# 2130634)

Industry/Other Documents

The following non-Sierra Wireless references are not included in your documentation package:

[5] FCC Regulations - Part 15 - Radio Frequency Devices

[6] IEC-61000-4-2 level 3

[7] IEC-61000-4-2 level (Electrostatic Discharge Immunity Test)

[8] Mobile Station (MS) Conformance Specification; Part 4: Subscriber Interface Module (Doc# 3GPP TS 11.10-4)

[9] PCI Express Mini Card Electromechanical Specification Revision 2.1

[10] Universal Serial Bus Specification, Rev 2.0

[11] Universal Serial Bus Specification, Rev 3.0

[12] JESD22-A114-B

[13] JESD22-C101

E: Acronyms

Table E-1: Acronyms and Definitions

Acronym or term	Definition
3GPP	3rd Generation Partnership Project
8PSK	Octagonal Phase Shift Keying
AGC	Automatic Gain Control
A-GPS	Assisted GPS
API	Application Programming Interface
BeiDou	BeiDou Navigation Satellite System A Chinese system that uses a series of satellites in geostationary and middle earth orbits to provide navigational data.
BER	Bit Error Rate—A measure of receive sensitivity
BLER	Block Error Rate
bluetooth	Wireless protocol for data exchange over short distances
CQI	Channel Quality Indication
COM	Communication port
CS	Circuit-switched
CSG	Closed Subscriber Group
CW	Continuous waveform
dB	Decibel = $10 \times \log_{10}(P1/P2)$ *P1 is calculated power; P2 is reference power* Decibel = $20 \times \log_{10}(V1/V2)$ *V1 is calculated voltage, V2 is reference voltage*
dBm	A logarithmic (base 10) measure of relative power (dB for decibels); relative to milliwatts (m). A dBm value will be 30 units (1000 times) larger (less negative) than a dBW value, because of the difference in scale (milliwatts vs. watts).
DC-HSPA+	Dual Carrier HSPA+
DCS	Digital Cellular System A cellular communication infrastructure that uses the 1.8 GHz radio spectrum.
DL	Downlink (network to mobile)
DRX	Discontinuous Reception
DSM	Distributed Shared Memory
DUT	Device Under Test
eICIC	Enhanced Inter-Cell Interference Coordination

Table E-1: Acronyms and Definitions (Continued)

Acronym or term	Definition
EIRP	Effective (or Equivalent) Isotropic Radiated Power
EMC	Electromagnetic Compatibility
EMI	Electromagnetic Interference
ERP	Effective Radiated Power
ESD	Electrostatic Discharge
FCC	Federal Communications Commission The U.S. federal agency that is responsible for interstate and foreign communications. The FCC regulates commercial and private radio spectrum management, sets rates for communications services, determines standards for equipment, and controls broadcast licensing. Consult www.fcc.gov.
FDD	Frequency Division Duplexing
FDMA	Frequency Division Multiple Access
feICIC	Further Enhanced Inter-Cell Interference Coordination
FER	Frame Error Rate—A measure of receive sensitivity.
firmware	Software stored in ROM or EEPROM; essential programs that remain even when the system is turned off. Firmware is easier to change than hardware but more permanent than software stored on disk.
FOTA	Firmware Over The Air—Technology used to download firmware upgrades directly from the service provider, over the air.
FOV	Field Of View
FSN	Factory Serial Number—A unique serial number assigned to the mini card during manufacturing.
Galileo	A European system that uses a series of satellites in middle earth orbit to provide navigational data.
GCF	Global Certification Forum
GLONASS	Global Navigation Satellite System—A Russian system that uses a series of 24 satellites in middle circular orbit to provide navigational data.
GMSK	Gaussian Minimum Shift Keying modulation
GNSS	Global Navigation Satellite Systems (GPS, GLONASS, BeiDou, and Galileo)
GPS	Global Positioning System An American system that uses a series of 24 satellites in middle circular orbit to provide navigational data.
Host	The device into which an embedded module is integrated
HSDPA	High Speed Downlink Packet Access
HSPA+	Enhanced HSPA, as defined in 3GPP Release 7 and beyond
HSUPA	High Speed Uplink Packet Access

Table E-1: Acronyms and Definitions (Continued)

Acronym or term	Definition
Hz	Hertz = 1 cycle/second
IC	Industry Canada
IF	Intermediate Frequency
IMEI	International Mobile Equipment Identity
IMS	IP Multimedia Subsystem—Architectural framework for delivering IP multimedia services.
inrush current	Peak current drawn when a device is connected or powered on
inter-RAT	Radio Access Technology
IOT	Interoperability Testing
IS	Interim Standard. After receiving industry consensus, the TIA forwards the standard to ANSI for approval.
ISIM	IMS Subscriber Identity Module (Also referred to as a SIM card)
LED	Light Emitting Diode. A semiconductor diode that emits visible or infrared light.
LHCP	Left-Hand Circular Polarized
LNA	Low Noise Amplifier
LPM	Low Power Mode
LPT	Line Print Terminal
LTE	Long Term Evolution—a high-performance air interface for cellular mobile communication systems.
MCS	Modulation and Coding Scheme
MHz	Megahertz = 10e6 Hz
MIMO	Multiple Input Multiple Output—wireless antenna technology that uses multiple antennas at both transmitter and receiver side. This improves performance.
NAS/AS	Network Access Server
NC	No Connect
NIC	Network Interface Card
NLIC	Non-Linear Interference Cancellation
NMEA	National Marine Electronics Association
OEM	Original Equipment Manufacturer—a company that manufactures a product and sells it to a reseller.
OFDMA	Orthogonal Frequency Division Multiple Access
OMA DM	Open Mobile Alliance Device Management—A device management protocol.

Table E-1: Acronyms and Definitions (Continued)

Acronym or term	Definition
OTA	'Over the air' (or radiated through the antenna)
PA	Power Amplifier
packet	A short, fixed-length block of data, including a header, that is transmitted as a unit in a communications network.
PCB	Printed Circuit Board
PCC	Primary Component Carrier
PCS	Personal Communication System A cellular communication infrastructure that uses the 1.9 GHz radio spectrum.
PDN	Packet Data Network
PMI	Pre-coding Matrix Index
PSS	Primary synchronisation signal
PST	Product Support Tools
PTCRB	PCS Type Certification Review Board
QAM	Quadrature Amplitude Modulation. This form of modulation uses amplitude, frequency, and phase to transfer data on the carrier wave.
QMI	Qualcomm MSM/Modem Interface
QOS	Quality of Service
QPSK	Quadrature Phase-Shift Keying
QPST	Qualcomm Product Support Tools
RAT	Radio Access Technology
RF	Radio Frequency
RI	Ring Indicator
roaming	A cellular subscriber is in an area where service is obtained from a cellular service provider that is not the subscriber's provider.
RSE	Radiated Spurious Emissions
RSSI	Received Signal Strength Indication
SCC	Secondary Component Carrier
SDK	Software Development Kit
SED	Smart Error Detection
Sensitivity (Audio)	Measure of lowest power signal that the receiver can measure.

Table E-1: Acronyms and Definitions (Continued)

Acronym or term	Definition
Sensitivity (RF)	Measure of lowest power signal at the receiver input that can provide a prescribed BER/BLER/ SNR value at the receiver output.
SG	An LTE signaling interface for SMS ("SMS over SGs")
SIB	System Information Block
SIM	Subscriber Identity Module. Also referred to as USIM or UICC.
SIMO	Single Input Multiple Output—smart antenna technology that uses a single antenna at the transmitter side and multiple antennas at the receiver side. This improves performance and security.
SISO	Single Input Single Output—antenna technology that uses a single antenna at both the transmitter side and the receiver side.
SKU	Stock Keeping Unit—identifies an inventory item: a unique code, consisting of numbers or letters and numbers, assigned to a product by a retailer for purposes of identification and inventory control.
SMS	Short Message Service. A feature that allows users of a wireless device on a wireless network to receive or transmit short electronic alphanumeric messages (up to 160 characters, depending on the service provider).
S/N	Signal-to-noise (ratio)
SNR	Signal-to-Noise Ratio
SOF	Start of Frame—A USB function.
SSS	Secondary synchronisation signal.
SUPL	Secure User Plane Location
TDD	Time Division Duplexing
TIA/EIA	Telecommunications Industry Association / Electronics Industry Association. A standards setting trade organization, whose members provide communications and information technology products, systems, distribution services and professional services in the United States and around the world. Consult www.tiaonline.org.
TIS	Total Isotropic Sensitivity
TRP	Total Radiated Power
UDK	Universal Development Kit (for PCI Express Mini Cards)
UE	User Equipment
UICC	Universal Integrated Circuit Card (Also referred to as a SIM card.)
UL	Uplink (mobile to network)
UMTS	Universal Mobile Telecommunications System
USB	Universal Serial Bus
USIM	Universal Subscriber Identity Module (UMTS)

Table E-1: Acronyms and Definitions (Continued)

Acronym or term	Definition
VCC	Supply voltage
VSWR	Voltage Standing Wave Ratio
WAN	Wide Area Network
WCDMA	Wideband Code Division Multiple Access (also referred to as UMTS)
WLAN	Wireless Local Area Network
ZIF	Zero Intermediate Frequency
ZUC	ZUC stream cypher

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